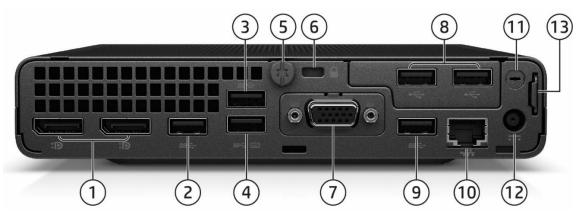
HP EliteDesk 800 G6 Desktop Mini Business PC



- 1. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 2. Type-A SuperSpeed USB 10Gbps signaling rate port
- Type-A SuperSpeed USB 5Gbps signaling rate port (charge support up to 5V/2.1A)
- 4. Combo Audio Jack with CTIA and headset support
- 5. Dual-state power button
- 6. Hard drive activity light

Overview

HP EliteDesk 800 G6 Desktop Mini Business PC



- 1. (2) Dual-Mode DisplayPort™ 1.4 (DP++)
- 2. Type-A SuperSpeed USB 5Gbps signaling rate port
- Type-A SuperSpeed USB 5Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
- Type-A SuperSpeed USB 10Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS) Cover release thumbscrew
- 5. Cover release thumbscrew
- 6. Standard cable lock slot (10 mm)
- 7. (1) Flex Port 1, choice of:
 - HDMI 2.0a
 Fiber NIC (100Mbps and
 - VGA 2.0a 1Gbps)¹
 - DisplayPort™ 1.4
 SerialPort (AMO only)
 - Thunderbolt 3 (AMO only)
 - Type-C[™] SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort[™] Alt Mode and 100W Power Intake
 - Intel® I225-LM 2.5 Gigabit Network Connection LOM (non-vPro)
 - Dual Type A SuperSpeed USB 10Gbps signaling rate port

- 8. (1) Flex Port 2, choice of:
 - VR Ready NVIDIA GTX 1660 Ti discrete GPU
 - Dual Type-A Hi-Speed USB 480Mbps signaling rate port
 - SerialS-232
- 9. Type-A SuperSpeed USB 10Gbps signaling rate port
- 10. RJ45 network connector
- 11. External WLAN antenna opening
- 12. Power connector
- 13. Retractable Padlock loop

Not Shown

Slots (1) Internal M.2 2230 connector for WLAN

(2) Internal M.2 SSD storage 2242 and 2280 connector

Bays (1) 2.5- inch SATA drive Bay (not available on 95W processor)

Mounting Support for

- VESA Sleeve Standalone

- Quick Release Bracket

- B300/B500 Mounting bracket

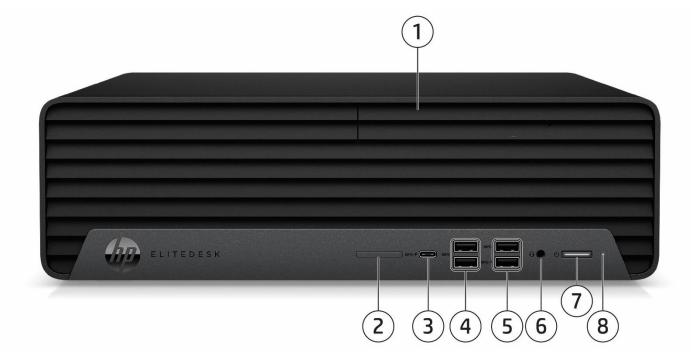
- Integrated Work Center Stand

1. Fiber NIC (100Mbps and 1Gbps) cards would not be available in some selected Europe countries and Korea.



Overview

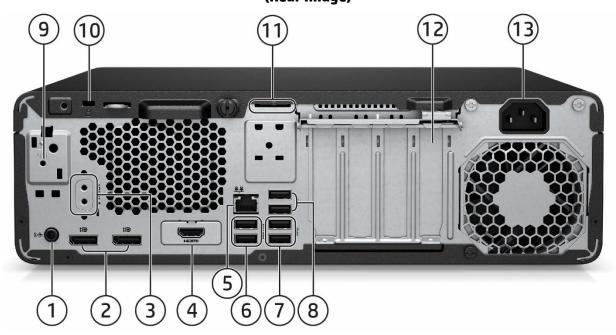
HP EliteDesk 800 G6 Small Form Factor Business PC



- 1. Optional Slim optical drive
- 2. Optional SD 4 Card Reader
- 3. Type-C[®] SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 4. Type A SuperSpeed USB 10Gbps signaling rate port (2)
- 5. Type A SuperSpeed USB 5Gbps signaling rate port (2) (1 with charge support up to 5V/1.5A)

- 6. Combo Audio Jack with CTIA and headset support
- 7. Dual-state power button
- 8. Hard drive activity light

HP EliteDesk 800 G6 Small Form Factor Business PC (Rear Image)



- 1. Audio line-out connector
- 2. Dual-Mode DisplayPort™ 1.4a (DP++) (2)
- 3. Optional Serial port (shown here not installed)
- 4. Optional port, choice of (shown here HDMI installed):
 - DisplayPort™
- Dual Type A SuperSpeed USB
- HDMI 2.0a
- 10Gbps signaling rate port
- VGA
- USB-C® SuperSpeed USB 10Gbps signaling rate port or serial port (USB-C® option has alt mode DisplayPort™ 1.4 and 15W output)
- 5. RJ45 network connector

- 6. Type A Hi-Speed USB 480 Mbps signaling rate port with wake from S4/S5 (2)
- 7. Type A SuperSpeed USB 10Gbps signaling rate port (2)
- 8. Type A SuperSpeed USB 5Gbps signaling rate port (2)
- 9. Optional Internal WLAN antenna cover (shown here not installed)
- 10. Standard cable lock slot
- 11. Optional intrusion sensor/hood lock (shown here not installed)
- 12. Optional Thunderbolt PCIe card with USB-C® (shown here not installed)
- 13. Power cord connector

Not shown

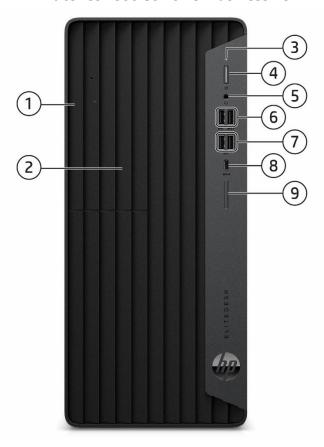
Slots

- (2) PCI Express x16 graphics connectors; one wired as an x4
- (2) PCI Express x1
- (2) internal M.2 SSD storage (2242 and 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

Bavs

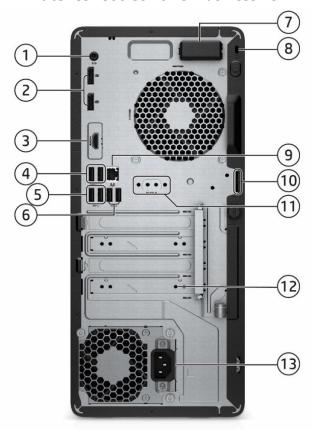
- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 9.5 mm slim optical drive bay

HP EliteDesk 800 G6 Tower Business PC



- 1. Optional Slim optical drive
- 2. External 5.25-inch Half-Height Drive Bay (behind bezel)
- 3. Hard drive activity light
- 4. Dual-state power button
- 5. Combo Audio Jack with CTIA and headset support
- Type A SuperSpeed USB 5Gbps signaling rate port (charge support up to 5V/1.5A) (2)
- 7. Type-A SuperSpeed USB 10Gbps signaling rate port (2)
- 8. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 9. Optional SD card 4.0 reader

HP EliteDesk 800 G6 Tower Business PC



5.5

- 1. Audio line-out jack for powered audio devices
- 2. Dual-Mode DisplayPort™ 1.4 (DP++) (2)
- 3. Optional port, choice of (shown here HDMI installed):
 - DisplayPort™ 1.4
 - HDMI 2.0a
- Dual Type A SuperSpeed USB 10Gbps signaling rate port
- VGA
- USB-C® SuperSpeed USB 10Gbps signaling rate port or serial port (USB-C® option has alt mode DisplayPort™ 1.4 and 15W output)
- 4. Type A Hi-Speed USB 480 Mbps signaling rate port with wake from S4/S5 (2)
- 5. Type A SuperSpeed USB 10Gbps signaling rate port (2)

- 6. Type A SuperSpeed USB 5Gbps signaling rate port (2)
- Optional Internal WLAN antenna cover (shown here installed)
- 8. Standard cable lock slot
- 9. RJ-45 (network) jack
- Optional intrusion sensor/hood lock (shown here not installed)
- 11. Optional serial port (shown here not installed)
- Optional Thunderbolt PCIe card with USB-C® (shown here not installed)
- 13. Power cord connector

Not shown

Slots

- (2) PCI Express x16 graphics connectors; one wired as an x4
- (2) PCI Express x1
- (2) internal M.2 SSD storage (2242 and 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

Bays

- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 5.25" half-height drive bay
- (1) 9.5mm slim optical drive bay



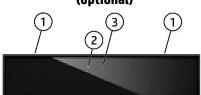
Overview

HP EliteOne 800 G6 24 & 27 All-in-One*



1. Camera (optional)

Front / Rear facing 5MP Webcam (optional)

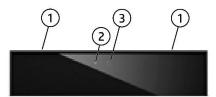


- Dual Microphones
 Webcam Light
- 3. Front / Rear facing 5MP Webcam

Speakers (optional)

5MP Webcam (optional)

2.



- 1. Dual Microphones
- 2. Webcam Light
- 3. 5MP Webcam

5MP Webcam with Infrared (IR) Sensors (optional)



- 1. Dual Microphones
- 2. Webcam Light
- 3. IR/5MP Webcam
 - 4. IR Light

*Available Options: Touch, Non-Touch, HP Sure View (24" Display Only), and Discrete Graphics

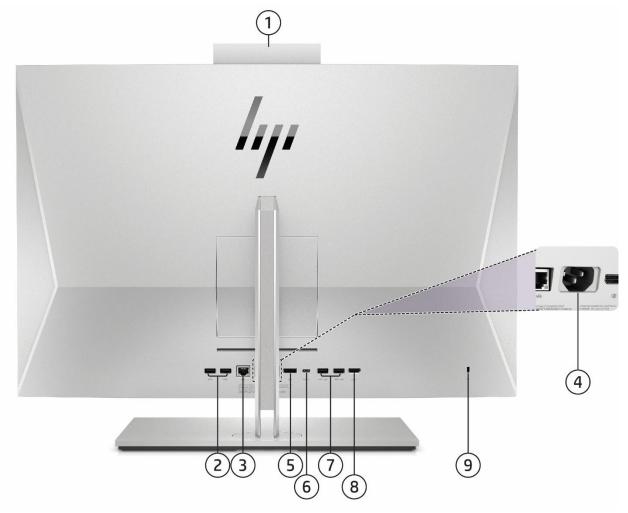


HP EliteOne 800 G6 24 & 27 All-in-One*



- 1. Type-A SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 2. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to (5V/3A)
- 3. Combo Audio Jack with CTIA and OMTP headset Support

HP EliteOne 800 G6 24 & 27 All-in-One

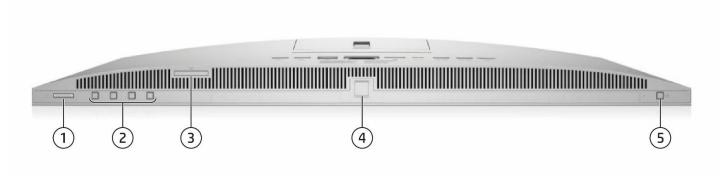


Rear components and rear ports

- 1. Camera (optional)
- 2. Type-A SuperSpeed USB 10Gbps signaling rate port (x2)
- 3. RJ-45 network connector/jack
- 4. Power Connector
- 5. Dual-Mode DisplayPort™1.4 (DP++)

- 6. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to (5V/3A)
- 7. Type-A SuperSpeed USB 5Gbps signaling rate port (x2)
- 8. HDMI-in 2.0a connector
- 9. Standard cable lock slot

HP EliteOne 800 G6 24 & 27 All-in-One



1. Dual-State Power button

- 2. OSD control buttons
- 3. SD card reader 4.0 (optional)

Bottom

- 4. Fingerprint Sensor (optional)
- 5. HP Sure View Button (optional on 23.8" only)

Not shown

Slots

- (1) internal M.2 PCIe x1 connector for optional wireless NIC
- (2) internal M.2 PCIe x4 connector for optional m.2 SSD

VESA

Support for VESA 100 mounting system on back of PC chassis (mounting hardware sold separately)



Features

AT A GLANCE

- Choice of four form factors: Tower, Small Form Factor, Desktop Mini and All-In-One
- HP developed and engineered UEFI V2.7 BIOS supporting security, manageability and software image stability
- Intel® Q470 chipset supporting Intel® 10th generation Core™ processors, featuring integrated Intel® UHD Graphics and Intel® vPro™ Technology (available with Core i3, Core i5, Core i7 and Core i9 processors) ^{1,4}
- Processors up to 65W on AiO
- Processors up to 95W on DM
- Processors up to 125W on DM, TWR and SFF
- Intel® Optane™ Memory H10 with Solid State Storage
- Intel® UHD graphics with optional discrete graphics configure systems to up to 7 monitors (TWR, SFF and DM 35W)
- Intel® Ethernet Connection I219LM GbE LOM integrated network connection
- Intel® Wi-Fi 6 + BT5 (802.11AX 2x2)
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM) (Transfer rates up to 2933 MT/s)²
- Support for up to 7 monitors via two standard DisplayPort™ 1.4 ports,a configurable Flex i/o port for video options and a
 discrete graphics card on TWRs, SFFs and DMs. AiO supports up to two additional monitors via DisplayPort™ or Type-C®
 USB in alternate mode.
- Configurable FlexPort which provides the following choices: HDMI 2.0, Serial, VGA, DisplayPort™ 1.4, or USB Type-C™ with DisplayPort™ 1.4 (USB Type-C® with DisplayPort™ 1.4 with Power Delivery {PD] on DMs), Thunderbolt 3.0 (port on DM, PCIe card on TWR, SFF) and Dual USB Type-A for (TWRs, SFFs and DMs). See Ports section for port availability by platform. FlexPort not supported on AIO.
- 2nd FlexPort available for configuration on the HP EliteDesk G6 Desktop Minis with the following ports: Serial, and Dual USB Type-A. FlexPort not supported on AIO.
- Configurable NVIDA® GeForce®VR ready discrete graphics card with (3) mini-DisplayPorts and (1) micro-HDMI video port for DM⁵ to support up to (7) monitors with minimum 4K resolution and option to connect up to (3) monitors with 5K resolution via graphics card.
- Configurable AMD® Radeon and NVIDA® GeForce® VR ready discrete graphics on AiO.5
- Configurable AMD® Radeon, NVIDA® GeForce® and NVIDA® Quadro® VR ready discrete graphics on TWR 5
- Compatibility with HP Mini-In-One 24 Display (800 G6 DM with 100W USB-C +PD option card)
- Compatible with HP Reverb VR Headset⁸ (AiO and TWR)
- Models can be configured with multiple data drives in a RAID array and support RAID 1 configured from factory.
- Zoom Rooms edition available (AiO, DM) with Win IoT
- Audio by Bang & Olufsen (AiO)
- Intel® Unite™ available (AiO, DM)⁶
- Integrated Low Blue Light Panels on AiO (excludes Sure View and Touch Models)
- Enhanced Security whit HP Security Suite (Refer to Security Section for details)
- ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.⁷
- CCC, CECP and SEPA Certified (TWR/SFF/DM/AiO)
- TCO Edge for AiO (TCO Edge not available for models with HP Sure View)
- TCO (TWR/SFF/DM)
- PC chassis and all internal components and modules are manufactured with low halogen content³
- Dust filter available for following platforms (35W DM, SFFs and TWRs)
- All form factors undergo up to 13 MIL-STD tests⁹
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1 /UL62368-1) / CSA (CSA C22.2 No.60950-1-07 / CSA C22.2 No.62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)
- Fiber NIC (100Mbps and 1Gbps) cards would not be available in some selected European countries and Korea.
- 1. Multi core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

 2. Maximum transfer rate only available with Intel® Core i7 and Core i9 Processors.



Features

- 3. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.
- 4. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependant on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with with future "virtual appliances" is yet to be determined.
- 5. VR-ready as optional feature, requires specific configuration to support.
- 6. Intel® Unite™ must be configured at the factory.
- 7. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.
- 8. Availability may vary by country.
- 9. MIL-STD drop test not performed for All-in-Ones. MIL-STD testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective feature's sections

PRODUCT NAME

HP EliteDesk 800 G6 Tower PC

HP EliteDesk 800 G6 Small Form Factor PC

HP EliteDesk 800 G6 Desktop Mini PC

HP EliteOne 800 G6 24 All-in-One PC

HP EliteOne 800 G6 27 All-in-One PC

OPERATING SYSTEM

Preinstalled Windows 11 Pro¹

Windows 11 Pro Education1

Windows 11 Home - HP recommends Windows 11 Pro for business1

Windows 11 Home Single Language - HP recommends Windows 11 Pro for business1

Windows 10 Pro^{1,2}

Windows 10 Pro Education^{1,2}

Windows 10 Home - HP recommends Windows 11 Pro for business^{1,2}

Windows 10 Home Single Language - HP recommends Windows 11 Pro for business^{1,2}

FreeDOS

Web-supported only Windows 10 Pro (available through downgrade rights from Windows 11 Pro)^{1,3}

- 1. Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).
- 2. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed interneet and Microsoft account required. ISP fees apply and additional requirements may apply over time for updates. See http://www.windows.com.
- 3. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

NOTE: HP tested Windows 10, version 1909 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282.



Features

SUPPORTED VERSIONS

HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282

CHIPSET

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	
Intel® Q470 PCH-H− vPro™	X	X	X	X	l

PROCESSORS

Intel® 10 th Generation Core™ Processors	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Core™ i9 10900K Processor with Intel® UHD Graphics 630 (3.7GHz, up to 5.3 GHz with Intel® Turbo Boost³, 20MB cache, 10 cores) 125W¹,²,⁴ Supports Intel® vPro™ Technology⁴	х	х	х	
Intel® Core™ i9 10900 Processor with Intel® UHD Graphics 630 (2.8GHz, up to 5.2 GHz with Intel® Turbo Boost³, 20MB cache, 10 cores) 65W¹,² Supports Intel® vPro™ Technology⁴	х	х	x	х
Intel® Core™ i9 10900T Processor with Intel® UHD Graphics 630 (1.9GHz, up to 4.6 GHz with Intel® Turbo Boost³, 20MB cache, 10cores) 35W¹,² Supports Intel® vPro™ Technology⁴	х			
Intel® Core™ i7 10700K Processor with Intel® UHD Graphics 630 (3.8 GHz, up to 5.1 GHz with Intel® Turbo Boost³, 16MB cache, 8 cores) 125W¹,²,⁴ Supports Intel® vPro™ Technology⁴	х	х	x	
Intel® Core™ i7 10700 processor with Intel® UHD Graphics 630 (2.9 GHz, up to 4.8 GHz with Intel® Turbo Boost³, 16 MB cache, 8 cores) 65W¹,² Supports Intel® vPro™ Technology⁴	х	х	х	х
Intel® Core™ i7 10700T Processor with Intel® UHD Graphics 630 (2.0 GHz, up to 4.5 GHz with Intel® Turbo Boost³,16MB cache, 8 cores) 35W¹,² Supports Intel® vPro™ Technology⁴	х			
Intel® Core™ i5 10600K processor with Intel® UHD Graphics 630 (4.1 up to 4.8 GHz with Intel® Turbo Boost³, 12 MB cache, 6 cores) 125W ^{1, 2,4} Supports Intel® vPro™ Technology⁴	X	x	x	
Intel® Core™ i5 10600 processor with Intel® UHD Graphics 630 (3.3 GHz, 12 MB cache, 6 cores) 65W ^{1, 2} Supports Intel® vPro™ Technology ⁴	X	Х	X	Х
Intel® Core™ i5 10600T processor with Intel® UHD Graphics 630 (2.4 GHz 12 MB cache, 6 cores) 35W ^{1, 2} Supports Intel® vPro™ Technology ⁴	х			
Intel® Core™ i5 10500 processor with Intel® UHD Graphics 630 (3.1 GHz, 12 MB cache, 6 cores) 65W ^{1, 2} Supports Intel® vPro™ Technology ⁴	X	х	x	x
Intel® Core™ i5 10500T processor with Intel® UHD Graphics 630 (2.3 GHz, 12 MB cache, 6 cores) 35W ^{1, 2} Supports Intel® vPro™ Technology ⁴	Х			



Features

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Core™ i5 10400 processor with Intel® UHD Graphics 630 (2.9 GHz, 12 MB cache, 6 cores) 65W ^{1, 2}	X	Х	X	X
Intel® Core™ i5 10400T processor with Intel® UHD Graphics 630 (2.0 GHz, 12 MB cache, 6 cores) 35W ^{1, 2}	Х			
Intel® Core™ i3 10325 processor with Intel® UHD Graphics 630 (3.9 GHz, 8MB cache, 4 cores) 65W ^{1, 2}	Х	х	Х	X
Intel® Core™ i3 10320 processor with Intel® UHD Graphics 630 (3.8 GHz, 8 MB cache, 4 cores) 65W¹	х	х	Х	х
Intel® Core™ i3 10305 processor with Intel® UHD Graphics 630 (3.8 GHz, 8MB cache, 4 cores) 65W¹	х	х	Х	х
Intel® Core™ i3 10305T processor with Intel® UHD Graphics 630 (3.0 GHz, 8MB cache, 4 cores) 35W¹	х			
Intel® Core™ i3 10300 processor with Intel® UHD Graphics 630 (3.7 GHz, 8 MB cache, 4 cores) 65W¹	х	х	Х	х
Intel® Core™ i3 10300T processor with Intel® UHD Graphics 630 (3.0 GHz, 8 MB cache, 4 cores) 35W¹	х			
Intel® Core™ i3 10105 processor with Intel® UHD Graphics 630 (3.7 GHz, 6MB cache, 4 cores) 65W¹	х	х	Х	х
Intel® Core™ i3 10105T processor with Intel® UHD Graphics 630 (3.0 GHz, 6MB cache, 4 cores) 35W¹	х			
Intel® Core™ i3 10100 processor with Intel® UHD Graphics 630 (3.6 GHz, 6 MB cache, 4 cores) 65W¹	X	х	Х	X
Intel® Core™ i3 10100T processor with Intel® UHD Graphics 630 (3.0 GHz, 6 MB cache, 4 cores) 35W¹	Х			

^{1:} Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a mea configuration surement of higher performance.

NOTE: Memory speed 2666 and 2933 MT/s can be achieved via two UDIMMs per channel (2DPC) when populated with the same part number.



^{2.} Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system.

^{3.} Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://www.intel.com/technology/turboboost for more information.

^{4.} Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Compatibility with future "virtual appliances" is yet to be determined.

Intel® Pentium® Processors	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
Intel® Pentium® Gold G6605 processor with Intel® UHD Graphics 630 (4.3GHz, 4 MB cache, 2 cores) 65W¹	Х	Х	Х	Х
Intel® Pentium® Gold G6600 processor with Intel® UHD Graphics 630 (4.2 GHz, 4 MB cache, 2 cores) 65W1	Х	X	X	X
Intel® Pentium® Gold G6505 processor with Intel® UHD Graphics 630 (4.2GHz, 4 MB cache, 2 cores) 65W¹	Х	X	X	X
Intel® Pentium® Gold G6505T processor with Intel® UHD Graphics 630 (3.6GHz, 4 MB cache, 2 cores) 35W¹	Х			
Intel® Pentium® Gold G6500 processor with Intel® UHD Graphics 630 (4.1 GHz, 4 MB cache, 2 cores) 65W1	Х	Х	Х	Х
Intel® Pentium® Gold G6500T processor with Intel® UHD Graphics 630 (3.5GHz, 4 MB cache, 2 cores) 35W¹	Х			
Intel® Pentium® Gold G6405 processor with Intel® UHD Graphics 610 (4.1GHz, 4 MB cache, 2 cores) 65W¹	Х	Х	Х	Х
Intel® Pentium® Gold G6405T processor with Intel® UHD Graphics 610 (3.5GHz, 4 MB cache, 2 cores) 35W¹	Х			
Intel® Pentium® Gold G6400 processor with Intel® UHD Graphics 610 (4.0 GHz, 4 MB cache, 2 cores) 65W1	Х	Х	Х	Х
Intel® Pentium® Gold G6400T processor with Intel® UHD Graphics 610 (3.4 GHz, 4 MB cache, 2 cores) 35W ¹	Х			

^{1:} Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a mea configuration surement of higher performance.



Features

GRAPHICS

Int	egrated Intel® Graphics	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	
	Intel® UHD Graphics 630 (integrated on 10 th gen Core i9/i7/i5/i3, Pentium® Gold G6600, G6500)	X	Х	Х	Х	
	Intel® UHD Graphics 610 (integrated on 10 th gen Pentium® Gold G6400, Celeron® G5900, G5920)	Х	х	Х	х	

tional Discrete Graphics Solutions	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
NVIDIA® GeForce® RTX 2080 Super 8GB FH 3DP HDMI Graphics Card*			Х	
NVIDIA® GeForce® RTX 2070 Super 8GB FH 3DP HDMI Graphics Card				X
NVIDIA® GeForce® RTX 2060 Super 8GB FH DP HDMI DVI-D Graphics Card*			х	
NVIDIA® Quadro P2200 5GB 4DP Graphics Card			Х	
NVIDIA® Quadro P1000 4GB 4mDP Graphics Card			X	
NVIDIA® Quadro P620 2GB Graphics Card		X	X	
NVIDIA® Quadro P400 2GB Graphics Card		Х	Х	
NVIDIA® GeForce® GTX 1660Ti 6GB HMDI, DP Graphics Card**	X			
AMD® Radeon™ RX 5300M 3GB NGC Graphics Card				X
AMD® Radeon™ RX 550X 4GB DP HDMI Graphics Card		Х	Х	
AMD® Radeon™ R7 430 2GB GDDR5 64bit DP+VGA***		Х	Х	
AMD® Radeon™ R7 430 2GB GDDR5 64bit 2DP		Х	Х	

^{*}Requires 550W chassis

NOTE: The TWR can support a single discrete graphics card up to 300W with a 550W Power Supply.

oters and Cables	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u> AiO</u>
HP DisplayPort™ Cable	Х	Х	Х	Х
HP DisplayPort™ to DVI-D Adapter	Х	Х	X	X
HP DisplayPort™ to HDMI True 4K Adapter	Х	Х	Х	Х
HP DisplayPort™ to VGA Adapter	Х	X	X	Х
HP USB to Serial Port Adapter	Х	Х	Х	Х
HP USB-C® to HDMI 4K Adapter	Х	X	X	Х
HP USB-C® to DisplayPort Adapter	Х	Х	X	Х
HP DVI Cable	Х			Х
HP HDMI Standard Cable Kit (HDMI)		Х	Х	Х
HP DVI Cable Kit	Х			Х
Micro HDMI to HDMI Adapter	Х	Х	X	
Mini DisplayPort to DisplayPort Adapter	Х			



^{**} Only available on the Desktop Mini with a 35W Processor and supports (3) Mini DP 1.4 Ports and (1) Micro —HDMI 2.0 port in order to drive up to 7 displays directly on the Desktop Mini.

^{***}Not available in all regions

Features

STORAGE

inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
500GB 7200RPM 3.5in SATA HDD		X	Х	
1TB 7200RPM 3.5in SATA HDD		X	Х	
2TB 7200RPM 3.5in SATA HDD		Х	Х	
inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
500GB 7200RPM 2.5in SATA HDD	X	X	Х	
1TB 7200RPM 2.5in SATA HDD	X	X	Х	
2TB 5400RPM 2.5in SATA HDD	X	X	Х	
500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD*	Х	X	Х	
500GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD*	х	х	Х	
PCIe NMVe Solid State Drives (SSD)	DM	SFF	TWR	AiO
256GB M.2 2280 PCIe NVMe SSD	X	X	X	Х
512GB M.2 2280 PCIe NVMe SSD	Х	Х	Х	Х
128GB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х	Х	Х
256GB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х	Х	Х
512GB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х	Х	Х
1TB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х	Х	Х
2TB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х	Х	Х
256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	Х	Х	Х	Х
512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	Х	Х	Х	Х
256GB Intel® Optane™ Memory H10 with Solid State Storage*	Х	Х	Х	Х
512GB Intel® Optane™ Memory H10 with Solid State Storage*	Х	Х	Х	Х
tical Disc Drives	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP 9.5mm Slim DVD-ROM Drive	-	Х	Х	
HP 9.5mm Slim DVD Writer Drive		Х	X	
HP 9.5mm Slim Blu-Ray Writer Drive		Х	Х	
dia Card Reader	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II)		Х	X	Х

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Features

MEMORY

Memory Type	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
DDR4-2666 (Transfer rates up to 2666 MT/s*), 2 SODIMM	Х			X
DDR4-3200 (Transfer rates up to 2933 MT/s**), 2 DIMM	Х			X
DDR4-2666 (Transfer rates up to 2666 MT/s*), 4 SODIMM		X	X	
DDR4-3200 (Transfer rates up to 2933 MT/s**), 4 DIMM		Х	X	

NOTE*: for i5 and below processor. **NOTE****: for i7 and i9 processor.

- 1. Actual system speed is determined by the processor configured. See processor specifications for supported memory data rate.
- 2. Memory speed 2666 and 2933 MT/s can be achieved via two UDIMMs per channel (2DPC) when populated with the same part number.
- 3. All memory slot are customer accessible/upgradeable.
- 4. For system configured with more than 3GB of memory and a 32-bit operation system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

mory Configuration	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
4 GB (1 x 4 GB)	X	X	X	Х
8 GB (2 x 4 GB)	Х	X	X	Х
8 GB (1 x 8 GB)	X	X	X	Х
16 GB (2 x 8 GB)	X	X	X	Х
16 GB (1 x 16 GB)	Х	X	X	Х
32 GB (2 x 16 GB)	X	X	X	Х
32 GB (4 x 8 GB)		X	X	
32 GB (1 x 32 GB)	Х	X	Х	Х
64 GB (4 x 16 GB)		X	X	
64 GB (2 x 32 GB)	Х	Х	Х	Х
128 GB (4 x 32 GB)		Х	Х	





Features

NETWORKING/COMMUNICATIONS

Ethernet (RJ-45)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® I219-LM 1 Gigabit Network Connection LOM (vPro)	X	X	X	X
Intel® I225LM 2.5 Gigabit Network Connection LOM (optional)	X			
Intel® Ethernet I210-T1 PCIe x1 Gb Network Interface Card (optional)		Х	Х	

Wireless¹	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Wi-Fi 6 AX201 + BT5 (802.11AX 2x2 vPro, supporting gigabit file transfer speed)	Х	Х	Х	X
Intel® Wi-Fi 6 AX201 + BT5 (802.11AX 2x2 non-vPro, supporting gigabit file transfer speed)	X	х	Х	х
Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® + BT5	Х	Х	Х	Х

^{1.} Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ax WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the PC to communicate with 802.11ax WLAN devices. Wi-Fi 6 requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported.



Features

KEYBOARDS AND POINTING DEVICES

oards	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP Wired Desktop 320K Keyboard	Х	Х	X	Х
HP USB Premium Keyboard	Х	Х	X	Х
HP USB and PS/2 Washable Keyboard ¹	Х	Х	Х	Х
HP USB Business Slim Smart Card (CCID) Keyboard	Х	Х	Х	Х
HP USB Keyboard	Х	Х	X	Х
HP PS/2 Business Slim Keyboard ¹		Х	X	
HP Wireless Business Slim Keyboard and Mouse	Х	Х	Х	Х
HP USB Business Slim Antimicrobial Keyboard ²	Х	Х	Х	Х
HP Wireless Premium Keyboard and Mouse	Х	Х	Х	Х
HP USB Keyboard and Mouse Healthcare Edition	Х	Х	Х	Х

e	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP Wired Desktop 320M Mouse	X	Х	Х	X
HP PS/2 Mouse ¹		Х	Х	
HP USB Optical Mouse	X	Х	Х	X
HP USB Premium Mouse	X	Х	Х	X
HP USB 1000dpi Laser Mouse	X	Х	Х	X
HP USB and PS/2 Washable Mouse ¹	X	Х	Х	
Antimicrobial USB Mouse ²	X	Х	Х	X
HP USB Hardened Mouse ²	X	Х	Х	X
HP USB Fingerprint Reader Mouse	X	Х	Х	X

^{1.} PS/2 port not available on EliteOne 800 G6 AiOs and not available on any EliteDesk 800 G6 DMs

^{2.} Not available in all regions

Features

SECURITY

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
TPM 2.0 (FW: 7.85) endpoint security controller (Infineon SLB9670) shipped with Windows 10. Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.	х	х	х	х
Solenoid Lock & Intrusion Sensor		X	Х	
Intrusion Sensor for DM/AiO (integrated in the PCA, can be enabled/disabled through BIOS)	X			х
Support for chassis cable lock devices	X (10 mm or smaller)	х	х	х
Support for chassis padlocks devices	Х	X	Х	
HP Fingerprint Sensor (standard on 800 G6 AiO touch models and optional on non-touch models)				Х
SATA port disablement (via BIOS)	X	X	Х	
Serial, USB enable/disable (via BIOS)	X	X	Х	Х
Intel® Identify Protection Technology (IPT) ¹	X	X	Х	Х
Serial, parallel, USB enable/disable (via BIOS)	X	X	Х	Х
Optional USB Port Disable at factory (user configurable via BIOS)	X	X	Х	Х
Removable media write/boot control	X	X	Х	Х
Power-on password (via BIOS)	X	X	Х	Х
Setup password (via BIOS)	X	X	Х	Х

^{1.} Models configured with Intel® Core™ processors have the ability to utilize advanced security protection for online transactions. IPT, used in conjunction with participating web sites, provides double identity authentication by adding a hardware component in addition to the usual user name and password. IPT is initialized through an HP Client Security module.

PORTS

I/O F	Ports – Internal Ports	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	
	Internal SATA storage connector(s)	N/A	3	4	N/A	
	Internal SATA storage connector (Data and Power)	1	N/A	N/A	N/A	

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

tandard User Accessible Ports	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Type-A Hi-Speed USB		2 (rear)	2 (rear)	
Type-A SuperSpeed USB 5 Gbps signaling rate port	1 (front) 2 (rear)	2 front (1 fast charging), 2 rear	2 front (1 fast charging), 2 rear	2 rear
Type-A SuperSpeed USB 10 Gbps signaling rate port	1 (front) 2 (rear)	2 front; 2 rear	2 front; 2 rear	2 rear 1 side
Type-C [®] SuperSpeed USB 10 signaling rate Gbps port	1 (front)	1 (front)	1 (front)	1 rear 1 side



Video	2 DisplayPort™ 1.4 (rear)	2 DisplayPort™ 1.4 (rear)	1 DisplayPort™ 1.4 (rear)	For models with integrated graphics: 1 DisplayPort™ 1.4 (rear) 1 USB Type-C® with alt mode display or 15W output) (rear) 1 HDMI-In (rear) For models with discrete graphics: 1 DisplayPort™ 1.4 (rear) 1 USB Type-C® with alt mode display or 15W output) (rear) 1 HDMI-In (rear)
Audio	1 Combo Audio Jack with CTIA and headset support (front)	1 Universal Audio Jack with CTIA headset support (front)); 1 Audio-out (rear),	1 Universal Audio Jack with CTIA headset support (front)); 1 Audio-out (rear),	1 CTIA/OMTP UAJ (side)
Network Interface	1 RJ45 (rear)	1 RJ45 (rear)	1 RJ45 (rear)	1 RJ45 (rear)

1) Flexible Port 1, choice of <u>one</u> of he following	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Type-A SuperSpeed USB 5 Gbps signaling rate port	2 (rear)	2 (rear)	2 (rear)	N/A
Type-C® SuperSpeed USB 10Gbps signaling rate port	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode and power intake via USB Type-C® Power Delivery up to 100W (rear)	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode (rear)	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode (rear)*	N/A
Thunderbolt™ 3	1 (rear)	1 (rear)	1 (rear)	N/A
Video		1 DisplayPort™ 1.4 <u>or</u> HDMI 2.0 <u>or</u> VGA (rear)	1 DisplayPort™ 1.4 <u>or</u> HDMI 2.0 <u>or</u> VGA (rear)	N/A
Serial (RS-232)	N/A	1 (rear)	1 (rear)	N/A
Fiber NIC Adapter	(1) 100Mbps NIC (rear) (1) 1 Gbps NIC (rear)			N/A
RJ-45 Ethernet NIC	(1) 2.5GbE(rear)			N/A

(1) Flexible Port 2, choice of <u>one</u> of the following:	<u>DM</u>	<u>SFF</u>	<u>MT</u>	<u>AiO</u>
Type-A USB	2 Hi-Speed USB (rear)			N/A
Serial (RS-232)	1 (rear)			N/A
Discrete Graphics	1 (rear)			N/A



Features

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 WLAN+BT Combo; (1) M.2 2242/2280 for PCIe SSD storage, (1) M.2 2280 for PCIe SSD storage
N/A	2	2	N/A
N/A	1	1	N/A
N/A	1 (up to 75W)	1 (up to 300W)	N/A
	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage) N/A	(1) M.2 PCle x1 2230 (for WLAN) (2) M.2 PCle x4 2280/2230 Combo (for storage) (1) M.2 PCle x1 2230 (for WLAN) (2) M.2 PCle x4 2280/2230 Combo (for storage) N/A 2 N/A 1	(1) M.2 PCIe x1 (1) M.2 PCIe x1 (230 (for WLAN) (230 (for WLAN) (2230 (for WLAN) (230 (for WLAN) <td< td=""></td<>

Bays	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
5.25" Half Height (External)	N/A	N/A	1	N/A
9mm Slim Optical Disc Drive (ODD)	N/A	1	1	N/A
SD Card Reader	N/A	1	1	1
2.5" Internal Storage Drive	1	1	1	N/A
3.5" Internal Storage Drive	N/A	2	2	N/A

SATA 2.5" internal storage drive cannot be selected if 2nd M.2, discrete graphic card, or 95W processor is selected.



Features

USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2



Features

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

HP BIOSphere Gen6¹
HP DriveLock & Automatic DriveLock²
BIOS Update via Network
HP Secure Erase³
Absolute Persistence Module⁴
Pre-boot Authentication
HP Wake on WLAN

Software

HP Desktop Support Utility HP JumpStart HP Privacy Settings HP Setup Integrated OOBE HP Support Assistant⁵ HP Noise Cancellation Software

Buy Office (sold separately) HP Smart Support⁶

Manageability Features

HP Driver Packs7

HP System Software Manager (SSM) (download)

HP BIOS Config Utility (BCU) (download)

HP Client Catalog (download)

HP Image Assistant Gen (download)

HP Manageability Integration Kit for Microsoft System Center Configuration Management Gen48

Ivanti Management Suite (download)9

HP Cloud Recovery¹⁰

HP Client Management Script Library (download)

Client Security Software

HP Client Security Suite Gen6¹¹
HP Power On Authentication
Windows Defender¹²

Security Management

Trusted Platform Module TPM 2.0 Embedded Security Chip shipped with Windows 10. (Common Criteria EAL4+ Certified).

SATA 0,1 port disablement (via BIOS)

Serial, USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

Support for chassis padlocks and cable lock devices

HP Sure Sense¹³

HP Sure Click¹⁴

HP Sure Start Gen6¹⁵

HP Sure Run Gen3¹⁶

HP Sure Recover Gen3¹⁷

- 1. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
- 2. Storage Drivelock does not work with Self Encrypting or Optane based storage.
- 3. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 4. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a



Features

limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

- 5. HP Support Assistant requires Windows and Internet access.
- 6. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.
- 7. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 8. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.
- 9. Ivanti Management Suite subscription required.
- 10. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.
- 11. HP Client Security Manager Gen6 requires Windows and is available on select HP Pro and Elite PCs.
- 12. Windows Defender Opt in Windows 10 and internet connection required for updates.
- 13. HP Sure Sense requires Windows 10.
- 14. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer, Google Chrome, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
- 15. HP Sure Start Gen6 is available on select HP PCs with Intel processors.
- 16. HP Sure Run Gen3 is available on select Windows 10 based HP Pro. Elite and Workstation PCs with select Intel® or AMD processors.
- 17. HP Sure Recover Gen3 is available on select HP PCs and requires an open network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.





Features

ENVIRONMENTAL & INDUSTRY

ENERGY STAR® certified models available

ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.

Low halogen (chassis, all internal components and modules)¹ TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit
 is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign
 matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the
 enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)¹

Non-operating: -22° to 149° F (-30° to 65° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50000ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.





HP EliteDesk 800 Desktop Mini G	i6 series
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HP EliteDesk 800 Desktop				
Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label Commission Regulation (EC) No 617/2013 (ErP Lot 3)			
System Configuration	The configuration used for the End Desktop model is based on a "Typ			e Emissions data for the
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz		100VAC, 50Hz
Normal Operation (Short idle)	8.9320 W 8.9410 W		W	8.9190 W
Normal Operation (Long idle)	6.3380 W 6.346		W	6.3280 W
Sleep	1.0520 W 1.1020 W		W	1.0320 W
Off	0.8210 W	0.8220	W	0.8200 W
	NOTE: Energy efficiency data listed is family. HP computers marked with the Environmental Protection Agency (EP, not offer ENERGY STAR® certified cont PC featuring a hard disk drive, a high of the control of the cont	e ENERGY STAR® Logo A) ENERGY STAR® spec figurations, then energ efficiency power supply	are compliant with ifications for comply efficiency data lead, and a Microsoft	n the applicable U.S. outers. If a model family does isted is for a typically configured Windows® operating system.
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz		100VAC, 50Hz
Normal Operation (Short idle)	30.4581 BTU/hr	30.4888 B	TU/hr	30.4138 BTU/hr
Normal Operation (Long idle)	21.6126 BTU/hr	21.6399 B		21.5785 BTU/hr
Sleep	3.5873 BTU/hr	3.7578 B1		3.5191 BTU/hr
Off	2.7996 BTU/hr 2.8030 BTU/hr 2.7962 BTU/hr NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.			•
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)	
Typically Configured – Idle	2.8			18.8
Fixed Disk – Random writes	2.8			18.8
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.			



Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC				
	Batteries used in the product do not contain:				
		ater the1ppm by weight			
		eater than 20ppm by weight			
	Battery size	: CR2032 (coin cell)			
	Battery type				
Additional Information	• This produ 2011/65/EC	ct is in compliance with the Restrictions of Hazardous S			
	Directive – 2				
		ct is in compliance with California Proposition 65 (State oxic Enforcement Act of 1986).	e of California; Safe Drinking		
		'AR® certified. EPEAT® 2019 registered where applicable	le. EPEAT ® registration varies by		
	country. See	http://www.epeat.net for registration status by count			
	2018.	rts weighing over 25 grams used in the product are ma	wheed per ICO11460 and ICO1042		
		rts weighing over 25 grams used in the product are ma ct contains a minimum of 35% post-consumer recyclec			
		post-consumer recycled plastic*	plastic (by wt.), including 10%		
		• This product is 95.1% recycle-able when properly disposed of at end of life.			
	*NOTE: Recyc	*NOTE: Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.			
Packaging Materials	External:	PAPER/Corrugated	562 g		
		PAPER/Molded pulp	74 g		
	Internal:	PLASTIC/Polyethylene low density	16 g		
Material Usage		does not contain any of the following substances in ex	cess of regulatory limits (refer		
	to the HP General Specification for the Environment at				
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):				
	• Asbestos				
	Certain Azo Colorants Certain Prominated Flame Petardants				
			rotardante in plactice		
	• Certain Bro	o Colorants ominated Flame Retardants – may not be used as flame	e retardants in plastics		
	• Certain Bro • Cadmium	ominated Flame Retardants – may not be used as flame	e retardants in plastics		
	Certain BroCadmiumChlorinate	ominated Flame Retardants – may not be used as flame d Hydrocarbons	e retardants in plastics		
	Certain BroCadmiumChlorinateChlorinate	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins	e retardants in plastics		
	Certain BroCadmiumChlorinateChlorinateFormaldeh	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde	e retardants in plastics		
	 Certain Bro Cadmium Chlorinate Chlorinate Formaldeh Halogenate 	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes	e retardants in plastics		
	 Certain Bro Cadmium Chlorinate Chlorinate Formaldeh Halogenate Lead carbo 	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes onates and sulfates	e retardants in plastics		
	 Certain Bro Cadmium Chlorinate Chlorinate Formaldeh Halogenate Lead carbo Lead and L 	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes	e retardants in plastics		
	 Certain Bro Cadmium Chlorinate Formaldeh Halogenate Lead carbo Lead and L Mercuric O 	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes onates and sulfates ead compounds			
	 Certain Bro Cadmium Chlorinate Formaldeh Halogenat Lead carbo Lead and L Mercuric O Nickel – fin carried by th 	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes onates and sulfates ead compounds xide Batteries iishes must not be used on the external surface design ie user.			
	 Certain Bro Cadmium Chlorinate Formaldeh Halogenate Lead carbo Lead and L Mercuric O Nickel – fin carried by th Ozone Dep 	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes onates and sulfates ead compounds xide Batteries iishes must not be used on the external surface designie user. leting Substances			
	Certain Bro Cadmium Chlorinated Chlorinated Formaldeh Halogenated Lead carbo Lead and L Mercuric O Nickel – finto carried by the Ozone Dep Polybromin	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes enates and sulfates ead compounds xide Batteries iishes must not be used on the external surface design ie user. leting Substances nated Biphenyls (PBBs)			
	Certain Bro Cadmium Chlorinated Chlorinated Formaldeh Halogenate Lead carbo Lead and L Mercuric O Nickel – fincarried by th Ozone Dep Polybromid	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes enates and sulfates ead compounds xide Batteries uishes must not be used on the external surface design te user. leting Substances nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs)			
	Certain Bro Cadmium Chlorinated Chlorinated Formaldeh Halogenate Lead carbo Lead and L Mercuric O Nickel — fin carried by th Ozone Dep Polybromid Polybromid	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes enates and sulfates ead compounds xide Batteries iishes must not be used on the external surface design ie user. leting Substances nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs) nated Biphenyl Oxides (PBBOs)			
	Certain Bro Cadmium Chlorinated Chlorinated Formaldeh Halogenate Lead carbo Lead and L Mercuric O Nickel — fin carried by th Ozone Dep Polybromid Polybromid Polychlorin	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes enates and sulfates ead compounds xide Batteries hishes must not be used on the external surface design he user. leting Substances hated Biphenyls (PBBs) hated Biphenyl Ethers (PBBEs) hated Biphenyl Oxides (PBBOs) hated Biphenyl (PCB)			
	Certain Bro Cadmium Chlorinated Chlorinated Formaldeh Halogenate Lead carbo Lead and L Mercuric O Nickel – fin carried by th Ozone Dep Polybromid Polybromid Polychlorir Polychlorir	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes enates and sulfates ead compounds xide Batteries eishes must not be used on the external surface design ie user. leting Substances enated Biphenyls (PBBs) enated Biphenyl Ethers (PBBEs) enated Biphenyl Oxides (PBBOs) enated Biphenyl (PCB) enated Terphenyls (PCT)	ed to be frequently handled or		
	Certain Bro Cadmium Chlorinated Chlorinated Formaldeh Halogenated Lead carbo Lead and L Mercuric O Nickel – find carried by the Ozone Dep Polybromid Polybromid Polychlorir Polychlorir Polyvinyl O	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes onates and sulfates ead compounds xide Batteries iishes must not be used on the external surface design ie user. leting Substances nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs) nated Biphenyl Oxides (PBBOs) nated Biphenyl (PCB) nated Terphenyls (PCT) ihloride (PVC) – except for wires and cables, and certain	ed to be frequently handled or		
	Certain Bro Cadmium Chlorinated Chlorinated Formaldeh Halogenated Lead carbo Lead and L Mercuric O Nickel – finto carried by the Ozone Dep Polybromid Polybromid Polychlorir Polychlorir Voluntarily r	ominated Flame Retardants – may not be used as flame d Hydrocarbons d Paraffins yde ed Diphenyl Methanes enates and sulfates ead compounds xide Batteries eishes must not be used on the external surface design ie user. leting Substances enated Biphenyls (PBBs) enated Biphenyl Ethers (PBBEs) enated Biphenyl Oxides (PBBOs) enated Biphenyl (PCB) enated Terphenyls (PCT)	ed to be frequently handled or		



Features

Packaging Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Features

HP EliteDesk 800 Small Form Factor G6 series

	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label • Commission Regulation (EC) No 617/2013 (ErP Lot 3)			
System Configuration	The configuration used for the End Desktop model is based on a "Typi	ergy Consumption and Declared Nois	se Emissions data for the	
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	12.479 watt	12.579 watt	12.291 watt	
Normal Operation (Long idle)	11.193 watt	11.306 watt	11.151 watt	
Sleep	0.675 watt	0.7	0.665 watt	
Off	0.479 watt	0.5	0.475 watt	
	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the mode family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family continuous offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® oper system.			
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	42.55339 BTU/hr	42.89439 BTU/hr	41.91231 BTU/hr	
Normal Operation (Long idle)	38.16813 BTU/hr	38.55346 BTU/hr	38.02491 BTU/hr	
Sleep	2.30175 BTU/hr	2.40064 BTU/hr	2.26765 BTU/hr	
Off	1.63339 BTU/hr	1.70841 BTU/hr	1.61975 BTU/hr	
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.			
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power Sound Pressure (L _{pAm} , decibels)		(L _{pAm} , decibels)	
Typically Configured – Idle	3.11		20.7	
Fixed Disk–Random writes	3.41		22.1	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.			



Batteries This battery(s) in this product comply with EU Directive 2006/66/EC			06/66/EC		
	Ratteries us	Batteries used in the product do not contain:			
		ater the1ppm by weight			
		eater than 20ppm by weight			
	June 1				
	Battery size: Battery type	: CR2032 (coin cell) :: Lithium			
Additional Information		ct is in compliance with the Restrictions of Haz	ardous Substances (RoHS) directive -		
	2011/65/EC				
	• This HP pro	oduct is designed to comply with the Waste Ele 1002/96/EC.	ectrical and Electronic Equipment (WEEE)		
	This produ	ct is in compliance with California Proposition (65 (State of California; Safe Drinking		
	Water and T	oxic Enforcement Act of 1986).	_		
		AR® certified. EPEAT® 2019 registered where a			
		www.epeat.net for registration status by cou			
		rts weighing over 25 grams used in the produc			
		ct contains a minimum of 35% post-consumer	recycled plastic (by wt.); Including 10%		
		post-consumer recycled plastic*	1.6		
	• This produ	• This product is 95.1% recycle-able when properly disposed of at end of life.			
	*NOTE: Pocuc	led plastic content percentage is based on the defin	sition cot in the IEEE 1690 1, 2019 standard		
Daaliaaina Matariala		· · · · · · · · · · · · · · · · · · ·			
Packaging Materials	External: Internal:	PAPER/Corrugated PAPER/Molded pulp	1158 g		
	internat.	PLASTIC/Polyethylene low density	340 g 28 q		
Material Usage	This product				
riateriat osage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at				
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):				
	• Asbestos				
	Certain Azo Colorants				
	Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics				
	• Cadmium				
	Chlorinated Hydrocarbons				
	Chlorinated Paraffins				
		• Formaldehyde			
	Halogenated Diphenyl Methanes				
	Lead carbonates and sulfates				
	Lead and Lead compounds				
	Mercuric Oxide Batteries Nickel				
	Nickel – finishes must not be used on the external surface designed to be frequently handled or				
		carried by the user. • Ozone Depleting Substances			
	Ozone Dep	leting Substances			
	Ozone Dep Polybromii	leting Substances nated Biphenyls (PBBs)			
	Ozone DepPolybromi	leting Substances nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs)			
	Ozone DepPolybromiiPolybromii	leting Substances nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs) nated Biphenyl Oxides (PBBOs)			
	Ozone Dep Polybromii Polybromii Polybromii Polychlorir	leting Substances nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs)			
	Ozone Dep Polybromii Polybromii Polybromii Polychlorir Polychlorir	leting Substances nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs) nated Biphenyl Oxides (PBBOs) nated Biphenyl (PCB)	d certain retail packaging has been		
	Ozone Dep Polybromii Polybromii Polybromii Polychlorir Polychlorir Polyvinyl C	leting Substances nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs) nated Biphenyl Oxides (PBBOs) nated Biphenyl (PCB) nated Terphenyls (PCT)	d certain retail packaging has been		
	Ozone Dep Polybromii Polybromii Polybromii Polychlorir Polychlorir Polyvinyl C voluntarily r Radioactiv	leting Substances nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs) nated Biphenyl Oxides (PBBOs) nated Biphenyl (PCB) nated Terphenyls (PCT) ihloride (PVC) – except for wires and cables, an			



Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:			
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging			
	materials.			
	Eliminate the use of ozone-depleting substances (ODS) in packaging materials.			
	Design packaging materials for ease of disassembly.			
	Maximize the use of post-consumer recycled content materials in packaging materials.			
	Use readily recyclable packaging materials such as paper and corrugated materials.			
	Reduce size and weight of packages to improve transportation fuel efficiency.			
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.			
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To			
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest			
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible			
	manner.			
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for			
	each product type for use by treatment facilities. This information (product disassembly			
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These			
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM			
	customers who integrate and re-sell HP equipment.			
	Global Citizenship Report			
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html			
	Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html			
	ISO 14001 certificates:			
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K			
	_Certificate.pdf			
	and			
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf			

Eco-Label Certifications & declarations	be labeled with one or more of the IT ECO declaration US ENERGY STAR® US Federal Energy Mana EPEAT® Gold registered in status in your country. TCO Certified China Energy Conservaties China State Environmenter Taiwan Green Mark Korea Eco-label Japan PC Green label	gement Program (FEMP) In the United States. See http://www	.epeat.net for registration
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a Typically Configured Desktop.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	11.67 W	11.24 W	11.53 W



Normal Operation	9.83 W	10.55	W	9.69 W
(Long idle)			0.86 W	
Sleep Off	0.84 W 0.81 W 0.57 W 0.53 W			0.86 W
	NOTE: Energy efficiency data listed is family. HP computers marked with the Environmental Protection Agency (EPA not offer ENERGY STAR® compliant coronfigured PC featuring a hard disk drisystem.	for an ENERGY STAR® ENERGY STAR® Logo A) ENERGY STAR® spec offigurations, then end tve, a high efficiency p	compliant product are compliant with ifications for com ergy efficiency data ower supply, and a	if offered within the model n the applicable U.S. puters. If a model family does a listed is for a typically a Microsoft Windows® operating
Heat Dissipation*	115VAC, 60Hz	230VAC,	50Hz	100VAC, 60Hz
Normal Operation (Short idle)	39.91 BTU/hr	38.44 BT	U/hr	39.43 BTU/hr
Normal Operation (Long idle)	33.62 BTU/hr	36.08 BT		33.14 BTU/hr
Sleep	2.87 BTU/hr	2.77 BT		2.94 BTU/hr
Off	1.95 BTU/hr	1.81 BT	U/hr	1.95 BTU/hr
	NOTE: Heat dissipation is calculated be one hour.	ased on the measured	l watts, assuming t	the service level is attained for
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)			
Typically Configured – Idle	3.3			21
Fixed Disk–Random writes Longevity and Upgrading	3.3			22
Batteries	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production. This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight			
	Battery size: CR2032 (coin cell) Battery type: Lithium			
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See www.epeat.net for registration status by country. According to IEEE 1680.1-2018. Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product contains a minimum of 35% post-consumer recycled plastic (by wt.); Including 10% ITE-derived post-consumer recycled plastic* This product is 95.1% recycle-able when properly disposed of at end of life. 			
Packaging Materials	External: PAPER/Corrugated			1114 g
	PAPER/Molded Puli			788 g



	Internal:	PLASTIC/Polyethylene low density - LDPE	44 q	
Material Usage		does not contain any of the following substances in ex		
3		neral Specification for the Environment at		
		hp.com/hpinfo/globalcitizenship/environment/pdf/gse	e.pdf):	
	 Asbestos 			
	• Certain Azo	Colorants		
	• Certain Bro	minated Flame Retardants – may not be used as flame	retardants in plastics	
	 Cadmium 			
	Chlorinated Hydrocarbons			
	 Chlorinated 			
	 Formaldehy 	5		
		ed Diphenyl Methanes		
		nates and sulfates		
		ead compounds		
		xide Batteries		
		ishes must not be used on the external surface designe	a to be frequently nanaled or	
	carried by the	leting Substances		
		nated Biphenyls (PBBs)		
		nated Biphenyl Ethers (PBBEs)		
		nated Biphenyl Oxides (PBBOs)		
		nated Biphenyl (PCB)		
		nated Terphenyls (PCT)		
		hloride (PVC) – except for wires and cables, and certain	retail packaging has been	
		emoved from most applications.	. 33	
	Radioactive	e Substances		
	• Tributyl Tin	n (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		
Packaging Usage	HP follows th	hese guidelines to decrease the environmental impact (of product packaging:	
	• Eliminate tl materials.	he use of heavy metals such as lead, chromium, mercui	y and cadmium in packaging	
	• Eliminate tl	he use of ozone-depleting substances (ODS) in packagi	ng materials.	
	 Design pack 	kaging materials for ease of disassembly.		
	Maximize tl	he use of post-consumer recycled content materials in	packaging materials.	
	Use readily	recyclable packaging materials such as paper and corr	ugated materials.	
	_	e and weight of packages to improve transportation fue	_	
		kaging materials are marked according to ISO 11469 an		
End-of-life Management and Recycling			ecycle or contact your nearest	
The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment is each product type for use by treatment facilities. This information (product disassed instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/instructions may be used by recyclers and other WEEE treatment facilities as well a customers who integrate and re-sell HP equipment. Global Citizenship Report			product disassembly ww.hp.com/go/recyclers. These	
		hp.com/hpinfo/globalcitizenship/gcreport/index.html		
	Eco-label cer		e La col	
		3.hp.com/us/en/hp-information/environment/ecolabel	s.html	
		hp.com/hpinfo/globalcitizenship/environment/pdf/PC_	_GBU_Product_Design_ISO_14K	
	_Certificate.p	pdf		
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Features

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteOne 800 G6 23.8-in All-in-One

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label
- Commission Regulation (EC) No 617/2013 (ErP Lot 3)

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the All-in-One PC model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	15.60 W	15.68 W	15.45 W
Normal Operation (Long idle)	5.57 W	5.65 W	5.41 W
Sleep	0.94 W	1.00 W	0.82 W
Off	0.84 W	0.87 W	0.81 W

NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	53.2028BTU/hr	53.4772 BTU/hr	52.691 BTU/hr
Normal Operation (Long idle)	19.02 BTU/hr	19.3 BTU/hr	18.5 BTU/hr
Sleep	3.2 BTU/hr	3.4 BTU/hr	2.8 BTU/hr
Off	2.9 BTU/hr	3 BTU/hr	2.8 BTU/hr

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions	Cound Douge	Cound Duccessus
(in accordance with	Sound Power	Sound Pressure
ISO 7779 and ISO 9296)	(L _{WAd} , bels)	(L _{pAm} , decibels)

Typically Configured – Idle		2.5	14
Fixed Disk – Random writes		2.5	15
Longevity and Upgrading Batteries	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: • 6 USB ports • 2 memory slots • 1 Mini PCIe half-length slot • 1 MXM 3.0 Type A - 35W slot • 1 mSATA slot • 1 2.5" internal bay supporting up to Two 2.5" hard drives (HDD/SSD/SED/SSHD) • 1 5.25" external supporting optical drive Spare parts are available throughout the warranty period and or for up to "5" years after the end of production. This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight		
	Battery size:	CR2032 (coin cell)	
Additional Information	Battery type:	: <u>Lithium</u> oduct is in compliance with the Restrictions of Hazar	
	 - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the gold level, see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product contains 51.7% post-consumer recycled plastic (by wt.) according to IEEE 1680.1-2018 standard, criterion 4.2.1.1. This product is 97.8% recycle-able when properly disposed of at end of life. 		
Packaging Materials	External:	PAPER/Corrugated	1.488 g
	Internal:	PLASTIC/Polyethylene Expanded - EPE	1.052 g
		ackaging material contains at least 90% recycled cor	
RoHS Compliance	The corrugated paper packaging materials contains at least 80% recycled content. HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.		



	To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf

Features

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteOne 800 G6 27 All-in-One PC

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label
- Commission Regulation (EC) No 617/2013 (ErP Lot 3)

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Allin-One PC model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	22.57 W	22.65 W	22.42 W
Normal Operation (Long idle)	6.35 W	6.44 W	6.19 W
Sleep	1.47 W	1.52 W	1.35 W
Off	0.88 W	0.89 W	0.84 W

Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	76.967 BTU/hr	77.2467 BTU/hr	76.4556 BTU/hr
Normal Operation (Long idle)	21.7 BTU/hr	22 BTU/hr	21.2 BTU/hr
Sleep	5 BTU/hr	5.2 BTU/hr	4.6 BTU/hr
Off	3 BTU/hr	3 BTU/hr	2.9 BTU/hr
1	· ·		· · · · · · · · · · · · · · · · · · ·

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions		Sound Power		Sound Pressure
(in accordance with		(Lwad, bels)		(L _{pAm} , decibels)
ISO 7779 and ISO 9296)		(=ma, octo)		(=p/mil) decircus,
Typically Configured – Idle		2.5		15
Fixed Disk – Random writes		2.6		16
Longevity and Upgrading	This product	can be upgraded, possibly extending	its useful life by	several years. Upgradeable
Longevity and opgrading	 features and/or components contained in the product may include: 6 USB ports 2 memory slots 1 Mini PCle half-length slot 1 MXM 3.0 Type A - 35W slot 1 mSATA slot 1 2.5" internal bay supporting up to Two 2.5" hard drives (HDD/SSD/SED/SSHD) 1 5.25" external supporting optical drive Spare parts are available throughout the warranty period and or for up to "5" years after the end o production.		/SSD/SED/SSHD)	
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain:		EC	
	Mercury grea Cadmium gre	iter the1ppm by weight eater than 20ppm by weight		
Battery size: CR? Battery type: Lit		Lithium		
Additional Information	dire	product is in compliance with the Rective - 2011/65/EC. HP product is designed to comply wiee) Directive - 2002/96/EC. product is in compliance with Califor	th the Waste Ele	ctrical and Electronic Equipment
 Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the gold l www.epeat.net 		standard at the gold level, see		
	 Plastics parts weighing over 25 grams used in the product are marked per ISO11469 ISO1043. 		·	
	This product contains 72.2% post-consumer recycled plastic (by wt.) according to IEEE 1680.1-2018 standard, criterion 4.2.1.1.			
		product is 98% recycle-able when p	roperly disposed	of at end of life.
Packaging Materials	External:	PAPER/Corrugated		1.510 g
	Internal:	PLASTIC/Polyethylene Expanded -	EPE	1.520 g
	The plastic p	oackaging material contains at least	xx% recycled cor	ntent.
	The corruga	ted paper packaging materials conta	ins at least xx%	recycled content.
RoHS Compliance	restrictions in products won	lies fully with materials regulations. n the European Union (EU) Restriction 'ldwide through the HP GSE. HP has c Europe, as well as China, India, and \	n of Hazardous S contributed to the	ubstances (RoHS) Directive to our
	We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.			



	We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see: HP RoHS position statement.
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html): - Asbestos - Certain Azo Colorants - Certain Brominated Flame Retardants – may not be used as flame retardants in plastics - Cadmium - Chlorinated Hydrocarbons - Chlorinated Paraffins - Bis(2-Ethylhexyl) phthalate (DEHP) - Benzyl butyl phthalate (BBP) - Dibutyl phthalate (BBP) - Diisobutyl phthalate (DIBP) - Formaldehyde - Halogenated Diphenyl Methanes - Lead carbonates and sulfates - Lead and Lead compounds - Mercuric Oxide Batteries - Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user Ozone Depleting Substances
	 Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental	For more information about HP's commitment to the environment:
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Features

SERVICE AND SUPPORT

HP EliteDesk 800 G6 Tower Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

- 15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

 17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteDesk 800 G6 Small Form Factor Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

- 15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

 17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteDesk 800 G6 Desktop Mini Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

- 15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

 17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Features

HP EliteOne 800 G6 24 & 27 All-in-One Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

- 15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

 17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance

ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.



Technical Specifications – Processors

PROCESSORS

Intel® 10th Generation Core™ Processors

All HP EliteDesk 800 G6 Business PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP EliteDesk and EliteOne 800 G6 Business PC.

Intel® Advanced Management Technology (AMT) v12 – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 12 includes the following advanced management functions:

- Support for configuration of Intel AMT 12.0 new capabilities
- · No reset after provisioning
- Support changes to BIOS table 130
- Support for Microsoft Windows Server 2012 R2
- Support for New Microsoft SQL Server Versions including Standard and Enterprise editions
- Support for Intel SSD Prop 2500 Series
- Support for Intel Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel products:
- Intel SSD Pro 2500 Series; Enterprise Digital Fence
- Intel Identity Protection Technology with One Time Password; Public Key Infrastructure; Multi Factor Authentication
- Intel Identity Protection Technology with Intel WiGig
- New Profile Editor and Profile Editor Plugin Interface
- New Required Permissions for Solutions Framework



Technical Specifications – Display Panel Specifications

DISPLAY PANEL SPECIFICATIONS

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch or optional Projected Capacitive Touch supports up to 10 touch-points

Non-Touch Support HW low blue light feature

TypeIPS WLED Backlit LCDActive area (mm)527.04 x 296.46Native Resolution (HxV)1920 x 1080

Refresh Rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.2745 x 0.2745

Contrast ratio 1000:1
Brightness* 250nits
Viewing angle (HxV) 178 ° x 178 °

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with the use of FRC technology

Color gamutNTSC 72%Anti-glareYes*Response Time14ms

Default color temperature Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) with HP Sure View (optional)

Type IPS WLED Backlit LCD
Active area (mm) 527.04 x 296.46
Native Resolution (HxV) 1920 x 1080

Refresh Rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.2745 x 0.2745

Contrast ratio 1000:1

Brightness* 285 nits (non-Privacy); 400 nits (Privacy) **Viewing angle (HxV)** 178° x 178° (non-Privacy); 80° x 178° (Privacy)

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with the use of FRC technology

Color gamutNTSC 72%Anti-glareYes*Response Time14ms

Default color temperature Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View



Technical Specifications – Display Panel Specifications

27.0" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch

Support HW low blue light feature

 Type
 IPS WLED Backlit LCD

 Active area (mm)
 597.888 x 336.312

 Native Resolution (HxV)
 1920 x 1080

Refresh Rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.3114 x 0.3114

Contrast ratio1000:1Brightness250nitsViewing angle (HxV)178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with the use of FRC technology

Color gamutNTSC 72%Anti-glareYes*Response Time14ms

Default color temperature Warm (6500K)

27.0" diagonal IPS widescreen WLED backlit LCD (2560 x 1440) Touch

Support HW low blue light feature

Type IPS WLED Backlit LCD
Active area (mm) 596.736 x 335.664
Native Resolution (HxV) 2560 x 1440

Refresh Rate 60 Hz @ 2560 x 1440

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.2331 x 0.2331

Contrast ratio 1000:1

Brightness* 250nits

Viewing angle (HxV) 178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum **Color support** Up to 16.7 million colors

Color gamutNTSC 72%Anti-glareNo*Response Time14ms

Default color temperature Warm (6500K)

2. For All in One only Intel® HD Graphics (integrated)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View



^{1.} All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Technical Specifications – Display Panel Specifications

Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)
	Portrait Adjustment	No portrait
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait
	Rotation (Swivel)	90° (±1°) (45 left, 45 right)
	Pivot	No pivot
Recline Stand:	Height - Vertical Adjustment	No height
	Tilt Angle	+36.5° to +58° (+/-1.5°)
	Rotation (swivel)	No swivel



Technical Specifications – Graphics

GRAPHICS

HP EliteDesk 800 G6 Desktop Mini Business PC

Intel® HD Graphics (integrated)

VGA Controller Integrated

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-

DisplayPort™ Stream Technology for a maximum of 3 displays connected to any output controlled by Intel®

Graphics

Supports HDMI 2.0a features

HDMI (optional) Supports HDCP 2.3

Supports audio over HDMI

VGA (optional) VGA output

USB-C® DP Alt Mode (optional) DisplayPort over the optional USB-C® module

The actual amount of maximum graphics memory can be >4GB. System memory is allocated

Memory for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth up to 10 bits/color

HEVC 10b Enc/Dec HW VP9 10b Dec HW

Graphics/Video API Support HDR

Rec. 2020

DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 4096 x 2160@60Hz

Nvidia® GeFORCE® GTX1660 Ti

Architecture Discrete GPU

Nvidia® GPU drives the integrated panel and all of the graphics output ports

DisplayPort Maximun pixel clock :1.3 GHz pixels per second

Maximun bandwidth: 25.92 Gbps per connector (FEC Disable)

HDMI Supports HDMI 2.0 features

Supports HDCP 2.2, HDR

Memory 6GByte, 192bit wide GDDR6

Maximum Color Depth up to 12 bits/color

Graphics/Video API Support DirectX 12

OpenGL 4.6

Display Port Support DP1.4(DSC1.2a)

Maximum pixel clock: 1.3 GHz pixels per second

Maximum bandwidth: 25.92 Gbps per connector (FEC Disable)

Max. Resolution (HDMI) 4096 x 2160@60Hz

Max. Resolution (DP) 5120 x 3200@60Hz Example of maximum resolutions with CVT-RB timings

Port Availability (3) Mini DP 1.4 ports and (1) Micro HDMI 2.0 port



Technical Specifications – Graphics

HP EliteDesk 800 G6 Tower Business PC

Intel® UHD Graphics (integrated)

VGA Controller Integrated

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-DisplayPort™ 1.4 Stream Technology for a maximum of 3 displays connected to any output controlled by Intel®

Supports HDMI 2.0a features

HDMI (optional) Supports HDCP 2.2

Supports BT2020 and HDR playback (7th Gen processors only)

VGA (optional) VGA ouput

USB-C® DP Alt Mode (optional) DisplayPort over the optional USB-C® module

The actual amount of maximum graphics memory can be >4GB. System memory is allocated Memory

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth up to 10 bits/color **HEVC 10b Enc/Dec HW**

VP9 10b Dec HW **Graphics/Video API Support HDR**

> Rec. 2020 DX12

640x480 60 Hz640x480 67Hz

640x480 72Hz 640x480 75Hz 720x400 70Hz 800x600 60Hz 800x600 75Hz 1024x768 60Hz 1024x768 75Hz

34" UHD Supported **Resolutions and Refresh** 1280x960 60Hz Rates. Other resolutions may also work.

1280x720 60Hz 1280x1024 60Hz 1280x1024 75Hz 1440x900 60Hz

1440x900 75Hz 1680x1050 60Hz 1920x1080 60Hz

3440x1440 60Hz (Native Resolution)

3440x1440 30Hz

Max. Resolution (VGA) 2048 x 1536@60Hz Max. Resolution (HDMI) 4096 x 2160@60Hz Max. Resolution (DP) 4096 x 2160@60Hz

NVIDIA® GeForce® RTX 2060 Super 8GB Graphics Card

Engine Clock 1650 MHz **Memory Clock** 7000 MHz Memory Size(width) 8 GB(256-bit) **Memory Type** 256M x 32 GDDR6 Max. Resolution(DVI) 2560x1600@60Hz Max. Resolution(HDMI) 4096x2160@60Hz Max. Resolution(DP) 7680x4320@60Hz

Multi Display Support 3 displays **HDCP Compliance** Yes



Technical Specifications – Graphics

Rear I/O connectors(bracket) DVI+HDMI+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <175W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

AMD® Radeon™ RX 550X 4 GB FH PCIe x16

Engine Clock1183MHzMemory Clock6 GbpsMemory Size(width)4 GB(128-bit)Memory TypeGDDR5

 Max. Resolution(HDMI)
 4096x2160 @ 60Hz

 Max. Resolution(DP)
 5120x2880 @ 60Hz

Multi Display Support 2 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) HDMI, DPx2

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP (low profile) PCB with FH/LP bracket

AMD® Radeon™ RX 580 8GB GDDR5 Graphics Card

 Engine Clock
 1266 MHz

 Memory Clock
 4000 MHz

 Memory Size(width)
 8 GB (256-bit)

 Memory Type
 256M x 32 GDDR5

 Max. Resolution(HDMI)
 4096x2160@60Hz

 Max. Resolution(DP)
 5120x3200@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) HDMI + DPx3

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <150W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 2080 Super 8GB GDDR6

 Engine Clock
 1815 MHz

 Memory Clock
 7750 MHz

 Memory Size(width)
 8GB (256-bit)

 Memory Type
 256M x 32 GDDR6

 Max. Resolution(Virtual Link)
 3840 x 2160@60Hz

 Max. Resolution(HDMI)
 4096 x 2160@60Hz

 Max. Resolution(DP)
 7680 x 4320@60Hz

Multi Display Support 4 displays
HDCP Compliance Yes

Rear I/O connectors(bracket) DPx3 + HDMI + Virtual Link



Technical Specifications – Graphics

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <285W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 2070 Super 8GB GDDR6

 Engine Clock
 1620 MHz

 Memory Clock
 7000 MHz

 Memory Size(width)
 8GB (256-bit)

 Memory Type
 256M x 32 GDDR6

 Max. Resolution(Virtual Link)
 3840 x 2160@60Hz

 Max. Resolution(HDMI)
 4096 x 2160@60Hz

 Max. Resolution(DP)
 7680 x 4320@60Hz

HDCP Compliance Yes

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <210W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® Quadro P620 2GB Graphics Card

Engine Clock1354 MHzMemory Clock2500 MHzMemory Size(width)2GB (128-bit)Memory Type128M x 32 GDDR5Max. Resolution(DP)5120x2880@60Hz

Multi Display Support4 displaysHDCP ComplianceYesRear I/O connectors(bracket)mDPx4

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <40W

PCB form-factor with bracket LP PCB with LP bracket

NVIDIA® Quadro P400 2GB Graphics Card

 Engine Clock
 1252 MHz

 Memory Clock
 2000 MHz

 Memory Size(width)
 2GB (64-bit)

 Memory Type
 256M x 32 GDDR5

 Max. Resolution(DP)
 5120x2880@60Hz

Multi Display Support 3 displays
HDCP Compliance Yes
Rear I/O connectors(bracket) mDPx3

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <30W

PCB form-factor with bracket LP PCB with LP bracket



Technical Specifications – Graphics

AMD® Radeon™ R7 430 2GB VGA+DP 64bit Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)2 GB(64-bit)Memory Type256M x 32 GDDR5Max. Resolution(HDMI)2048x1536

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support2 displaysHDCP ComplianceYes

Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 2DP 64 bit Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)2 GB(64-bit)Memory Type256M x 32 GDDR5Max. Resolution(DP)4096x2160@60Hz

Multi Display Support 2 displays

HDCP Compliance yes
Rear I/O connectors(bracket) DPx2

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

HP EliteDesk 800 G6 Small Form Factor Business PC

Intel® HD Graphics (integrated)

VGA Controller Integrated

DisplayPort™ 1.4 Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and

Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by

Intel® Graphics

HDMI (optional) Supports HDMI 2.0a features

Supports HDCP 2.2 Supports audio over HDMI

VGA (optional) VGA Output

USB-C[®] **DP Alt Mode (optional)** DisplayPort over the optional USB-C[®] module

Memory The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide

an optimal balance between graphics and system memory use.

Maximum Color Depth up to 10 bits/color
Graphics/Video API Support HEVC 10b Enc/Dec HW

VP9 10b Dec HW

HDR Rec. 2020 DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz



Technical Specifications – Graphics

Max. Resolution (DP) 4096 x 2160@60Hz

AMD® Radeon™ R7 430 2GB VGA+DP 64bit Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)1 GB(64-bit)Memory Type256M x 32 GDDR5Max. Resolution(HDMI)2048x1536

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support 2 displays

HDCP Compliance Yes
Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 2DP 64 bit Graphics Card

 Engine Clock
 780 MHz

 Memory Clock
 1100 MHz

 Memory Size(width)
 1 GB(64-bit)

 Memory Type
 256M x 32 GDDR5

 Max. Resolution(DP)
 4096x2160@60Hz

Multi Display Support2 displaysHDCP ComplianceyesRear I/O connectors(bracket)DPx2

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ RX550 4 GB PCIe x16

Engine Clock 1183MHz

Memory Clock 6 Gbps

Memory Size(width) 4 GB(128-bit)

Memory Type GDDR5

 Max. Resolution(HDMI)
 4096x2160 @ 60Hz

 Max. Resolution(DP)
 5120x2880 @ 60Hz

Multi Display Support2 displaysHDCP ComplianceYesRear I/O connectors(bracket)HDMI, DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP (low profile) PCB with FH/LP bracket



Technical Specifications – Graphics

AMD Radeon™ 520 1GB Graphics Card

 Engine Clock
 780 MHz

 Memory Clock
 1100 MHz

 Memory Size(width)
 1 GB (32-bit)

 Memory Type
 256M x 32 GD

 Memory Type
 256M x 32 GDDR5

 Max. Resolution(DP)
 2048x1536@60Hz

Multi Display Support2 displaysHDCP ComplianceYes

Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket



Technical Specifications – Graphics

HP EliteOne 800 G6 23.8-in All-in-One

Intel® UHD Graphics (integrated)

VGA Controller Integrated

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-DisplayPort™ 1.4

Stream Technology for a maximum of 3 displays (including the integrated panel and all

attached displays)

HDMI-in Support HDMI-In

The actual amount of maximum graphics memory can be >4GB. System memory is allocated Memory

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

up to 10 bits/color **Maximum Color Depth**

HEVC 10b Enc/Dec HW

VP9 10b Dec HW

Graphics/Video API Support HDR

> Rec. 2020 DX12

Max. Resolution (VGA) 2048 x 1536@60Hz Max. Resolution (HDMI) 4096 x 2160@60Hz Max. Resolution (DP) 4096 x 2160@60Hz

AMD® R19M

Discrete GPU **Architecture**

AMD® GPU drives the integrated panel and all of the graphics output ports

DisplayPort Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3

link rates and Multi-Stream Technology for a maximum of 53 displays (including the integrated

panel and all attached displays)

Support HDMI-In HDMI-In

3GByte, 128bit wide GDDR6 Memory

Maximum Color Depth up to 12 bits/color

Graphics/Video API Support DirectX 12

> OpenCL 2.0 OpenGL 4.5

AMD® Unified Video Decoder (UVD)

Max. Resolution (DP) 4096 x 2160@60Hz

Nvidia ® N18E-G2R

Architecture Discrete GPU

NVidia® GPU drives the integrated panel and all of the graphics output ports

DisplayPort Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3

link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated

panel and all attached displays)

HDMI-In Support HDMI-In

Memory 8GByte, 128bit wide GDDR6

Maximum Color Depth up to 12 bits/color

Graphics/Video API Support DirectX 12

> OpenCL 2.0 OpenGL 4.5

Max. Resolution (DP) 4096 x 2160@60Hz



Technical Specifications – Storage

STORAGE

500GB 7200RPM 3.5in SATA HDD

500GB Capacity **Rotational Speed** 7,200 rpm Interface SATA 6.0 Gb/s

Buffer Size 32MB

Logical Blocks 976,773,168 **Seek Time** 11 ms (Average) Height 1in/2.54cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB 7200RPM 3.5in SATA HDD

Capacity 1TB

Rotational Speed 7,200 rpm Interface SATA 6 Gb/s **Buffer Size** 64MB

Logical Blocks 1,953,525,168 **Seek Time** 11 ms (Average) Height 1in/2.54cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

41° to 131° F (5° to 55° C) **Operating Temperature**

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2TB 7200RPM 3.5in SATA HDD

2TB Capacity

Rotational Speed 7,200 rpm Interface SATA 6 Gb/s **Buffer Size 64MB**

Logical Blocks 3,907,050,336 **Seek Time** 11 ms (Average) Height 1.028in/26.11mm

Media diameter: 3.5 in/88.9 mm Width (nominal)

Physical size: 4 in/102 mm

Operating Temperature 41° to 131° F (5° to 55° C)



Technical Specifications – Storage

500GB 7200RPM 2.5in SATA HDD

Capacity 500GB **Rotational Speed** 7,200 rpm Interface SATA 6 Gb/s Up to 128MB **Buffer Size Logical Blocks** 976,773,168 **Seek Time** 12 ms (Average) 0.283in/7.2mm (Max.) Height Width (nominal) 2.75in/70mm (nominal) 41° to 131° F (5° to 55° C) **Operating Temperature**

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB 7200RPM 2.5in SATA HDD

Capacity 1TB

Rotational Speed 7,200 rpm

Interface SATA 6 Gb/s

Buffer Size Up to 128MB

Logical Blocks 1,953,525,168

Seek Time 12 ms (Average)

 Height
 0.283in/7.2mm (Max)

 Width (nominal)
 2.75in/70mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2TB 5400RPM 2.5in SATA HDD

Capacity 2TB

Rotational Speed 5,400 rpm
Interface SATA 6 Gb/s
Buffer Size 128MB

Logical Blocks 3,907,050,336 **Seek Time** 12 ms (Average)

Height0.374in/9.5mm (nominal)Width (nominal)2.75in/70mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)



Technical Specifications – Storage

500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity 500GB

Architecture Self-Encrypting (SED) Solid State Drive with SATA interface

Interface SATA 6 Gb/s
Buffer Size 128 MB
Logical Blocks 976,773,168
Seek Time 12 ms (Average)

Height0.283in/7.2mm (nominal)Width2.75in/70mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD

Capacity 500GB

Architecture Self-Encrypting (SED) Solid State Drive with SATA interface

InterfaceSATA 6 Gb/sBuffer Size128 MBLogical Blocks976,773,168Seek Time12 ms (Average)

Height0.283in/7.2mm (nominal)Width2.75in/70mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</td>Capacity256GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 780MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2



Technical Specifications – Storage

512GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10g
Capacity 512GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 860MB/sLogical Blocks1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q 128GB Capacity Height 2.38mm Length 80mm Width 22mm **Interface** PCIE Gen3 **Maximum Sequential Read** Up to 2800MB/s **Maximum Sequential Write** Up to 600MB/s

Logical Blocks

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

250,069,680

Features APST: ASPM L1.2: NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a Capacity 256GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 2700MB/s **Maximum Sequential Write** Up to 1000MB/s **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2



Technical Specifications – Storage

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10g
Capacity 512GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3

Maximum Sequential ReadUp to 2900MB/sMaximum Sequential WriteUp to 1100MB/sLogical Blocks1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q 1TB Capacity 2.38mm Height Length 80mm Width 22mm **Interface** PCIE Gen3 **Maximum Sequential Read** Up to 3480MB/s **Maximum Sequential Write** Up to 3037MB/s **Logical Blocks** 2,000,409,264

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM: ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a 2TB Capacity Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 3500MB/s **Maximum Sequential Write** Up to 3000MB/s **Logical Blocks** 3,907,029,168

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2



Technical Specifications – Storage

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight < 10g
Capacity 256GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3

Maximum Sequential ReadUp to 2700MB/sMaximum Sequential WriteUp to 1000MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight < 10q 512GB Capacity Height 2.38mm Length 80mm Width 22mm **Interface** PCIE Gen3 **Maximum Sequential Read** Up to 2900MB/s **Maximum Sequential Write** Up to 1100MB/s **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB Intel® PCIe® NVMe™ QLC + 16GB Intel® Optane™

Drive Weight < 10a Capacity 256GB Height 2.38mm Length 80mm Width 22mm Interface PCIe Gen3 **Maximum Sequential Read** Up to 1450MB/s **Maximum Sequential Write** Up to 500MB/s **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2



Technical Specifications – Storage

512GB Intel® PCIe® NVMe™ QLC + 32 GB Intel® Optane™

Drive Weight < 10g
Capacity 512GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIe Gen3

Maximum Sequential ReadUp to 2400MB/sMaximum Sequential WriteUp to 1300MB/sLogical Blocks1,000,215,215

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 9.5mm Slim DVD-ROM Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) Up to 0.31 lb (140g) without bezel

Read Speeds DVD+R/-R/+RW/

-RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X

Access time

(typical reads, including

settling)

Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions Temperature 41° to 122° F (5° to 50° C)

(operating - non-condensing) Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

 Weight (max)
 0.31 lb (140 g)

 Write Speeds
 DVD-R DL - Up to 6X DVD+R - Up to 8X

DVD+RW - Up to 8X



Technical Specifications – Storage

DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X

DVD-RW, DVD+RW - Up to 8X

DVD-R DL, DVD+R DL - Up to 8X **Read Speeds**

DVD+R, DVD-R - Up to 8X

DVD-ROM DL, DVD-ROM - Up to 8X

CD-ROM, CD-R - Up to 24X

CD-RW - Up to 24X

Access time

(typical reads, including

Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

settling)

Power

Stop Time 6 seconds (typical)

Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)

Environmental conditions (operating - non-condensing) Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim Blu-Ray Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 128 GB QL, 100 GB TL, 50 GB DL or 25 GB standard SL Dimensions ($W \times H \times D$) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.29 lb (132 g)

Write Speeds BD-R SL/DL Up to 6X

BD-R TL/QL Up to 4X BD-R Up to 6X BD-RE Up to 2X DVD-R Up to 8X DVD-R DL - Up to 6X DVD-RW Up to 6X DVD+R Up to 8X DVD+R DL - Up to 6X DVD+RW Up to 8X DVD-RAM Up to 5X CD-R Up to 24X CD-RW Up to 10X

Read Speeds BD-ROM Up to 6X

BD-R Up to 6X BD-RE SL/DL Up to 6X BD-RE TL Up to 4X DVD-ROM Up to 8X DVD-R SL/DL Up to 8X DVD-R Up to 8X DVD-RW Up to 8X DVD+R SL/DL Up to 8X

DVD+R Up to 8X DVD+RW Up to 8X



Technical Specifications – Storage

BDMV (AACS Compliant

Disc)

Up to 6x/2x (Read/Play) DVD-RAM Up to 5x **DVD-Video (CSS** Compliant Disc)

Up to 8x/4x (Read/Play) CD-R/RW/ROM Up to 24x

CD-DA (DAE) Up to 24X/10X (Read/Play)

Access time

Random BD-ROM: 205 ms (typical), DVD-ROM: 185 ms (typical), (typical reads, including CD-ROM: 165 ms (typical)

settling)

Full Stroke BD-ROM: 350 ms (typical), DVD-ROM: 345 ms (typical),

CD-ROM: 340 ms (typical)

Source Slimline SATA DC power receptacle **Power**

> DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC -1200 mA typical, 2000 mA maximum

Environmental conditions (operating - non-condensing) Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)





Technical Specifications – Networking and Communications

NETWORKING AND COMMUNICATIONS

Intel® I219-LM 1 Gigabit	Network Connection LOM (vPro)	
Connector	RJ-45	
System Interface	PCI (Intel proprietary) + SMBus	
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s	
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)	
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling (Hash Mode Only) Jumbo Frame 9K	
Power consumption	Cable Disconnetion: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW	
Power	ACPI compliant – multiple power modes	
Management	Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption	
Management Interface	Auto MDI/MDIX Crossover cable detection	
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status	
Security & Manageability	Intel® vPro® support with appropriate Intel® chipset components	

Intel® 1225-LM 2.5 Gigabit Ne	ntel® 1225-LM 2.5 Gigabit Network Connection LOM (non-vPro)	
Connector	RJ-45	
System Interface	PCI (Intel proprietary) + SMBus	
Data rates supported	1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)	
	2. 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)	
	3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40)	
	4. 2.5 Gbit/s operation(2.5GBASE-T; IEEE 802.3bz Clause 126)	
	5. Auto-Negotiation (Automatic Speed Selection)	
	Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s	



	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)	
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)	
	IEEE 802.3az EEE (Energy Efficient Ethernet)	
	IEEE 802.3i 10BASE-T	
	IEEE 802.3u 100BASE-TX	
	IEEE 802.3ab 1000BAE-T	
	IEEE 802.3bz 2.5GBASE-T	
Performance	TCP/IP/UDP Checksum Offload (configurable)	
	Protocol Offload (ARP & NS)	
	Large send offload and Giant send offload	
	Receiving Side Scaling	
	Jumbo Frame 9K	
Power consumption	Cable Disconnetion: 25mW	
	100Mbps Full Run: 450mW	
	1000bp Full Run: 1000mW	
	·	
	WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW	
Davies	WOL DISABLE(53/54/55): 25111W	
Power Management	ACPI compliant – multiple power modes	
	Situation-sensitive features reduce power consumption	
	Advanced link down power saving for reducing link down power consumption	
Management Interface	Auto MDI/MDIX Crossover cable detection	
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)	
	PXE 2.1 Remote Boot	
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))	
	Comprehensive diagnostic and configuration software suite	
	Virtual Cable Doctor for Ethernet cable status	
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components	

Intel® i210 10/100/1000 NIC	
RJ-45	
PCI (Intel proprietary) + SMBus	
10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)	



	Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support
	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable)
	Protocol Offload (ARP & NS)
	Large send offload and Giant send offload
	Receiving Side Scaling
	Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW
	100Mbps Full Run: 450mW
	1000bp Full Run: 1000mW
	WoL Enable(S3/S4/S5): 50mW
	WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption
	Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-
	on-LAN from off (Magic Packet only)
Security & Manageability	PXE 2.1 Remote Boot

Intel Wi-Fi 6 AX201 + BT5 (80	2.11ax 2x2, vPro, supporting gigabit file transfer speeds) vPro
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Features Wi-Fi 6 technology
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
	• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM



Security ³	• IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only			
	AES-CCMP: 128 bit in hardware			
	• 802.1x authentication			
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.			
	WPA2 certification			
	• IEEE 802.11i			
	• WAPI			
Network Architecture	Ad-hoc (Peer to Peer)			
Models	Infrastructure (Access Point Required)			
Roaming	IEEE 802.11 compliant roaming between access points			
Output Power ²	• 802.11b : +18.5dBm minimum			
•	• 802.11g: +17.5dBm minimum			
	• 802.11a : +18.5dBm minimum			
	• 802.11n HT20(2.4GHz) : +15.5dBm minimum			
	• 802.11n HT40(2.4GHz) : +14.5dBm minimum			
	• 802.11n HT20(5GHz): +15.5dBm minimum			
	• 802.11n HT40(5GHz): +14.5dBm minimum			
	• 802.11ac VHT80(5GHz): +11.5dBm minimum			
	• 802.11ac VHT160(5GHz) : +11.5dBm minimum			
	• 802.11ax HT40(2.4GHz) : +10dBm minimum			
	• 802.11ax VHT160(5GHz) : +10dBm minimum			
Power Consumption	• Transmit mode: 2.0 W			
	• Receive mode: 1.6 W			
	• Idle mode (PSP) 180 mW (WLAN Associated)			
	• Idle mode: 50 mW (WLAN unassociated)			
	• Connected Standby: 10mW			
	• Radio disabled: 8 mW			
Power Management	ACPI and PCI Express compliant power management			
	802.11 compliant power saving mode			
Receiver Sensitivity ³	•802.11b, 1Mbps : -93.5dBm maximum			
necesses seminately	•802.11b, 11Mbps: -93.3dBiff flaxifidiff			
	• 802.11a/g, 6Mbps : -86dBm maximum			
	• 802.11a/g, 54Mbps : -72dBm maximum			
	• 802.11n, MCS07 : -67dBm maximum			
	• 802.11n, MCS15 : -64dBm maximum			
	• 802.11ac, MCS0 : -84dBm maximum			
	• 802.11ac, MCS9 : -59dBm maximum			
	•802.11ax, MCS11(HT40): -59dBm maximum			
	•802.11ax, MCS11(H140)59ubit maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum			
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure			
	ringin erriciency uncerina with spatial arversity, mounted in the display encessare			
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN			
	MIMO communications and Bluetooth communications			
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface			
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm			
	2. Type 1216: 1.67 x 12.0 x 16.0 mm			
Weight	1. Type 2230 : 2.8g			
Weight				
Operating Voltage	2. Type 126: 1.3g			
Operating Voltage	2. Type 126: 1.3g 3.3v +/- 9%			
Operating Voltage Temperature	2. Type 126: 1.3g 3.3v +/- 9% Operating 14° to 158° F (-10° to 70° C)			
Temperature	2. Type 126: 1.3g 3.3v +/- 9% Operating			
<u> </u>	2. Type 126: 1.3g 3.3v +/- 9% Operating			
Temperature	2. Type 126: 1.3g 3.3v +/- 9% Operating			



LED Activity	LED Amber – Radio OFF; LED White – Radio ON
HP Integrated Module with Bluet	ooth® 4.0/4.1/4.2/5.0/5.1 Wireless Technology
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps
Data Kates and Throughput	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW
	Peak (Rx) 230 mW
	Selective Suspend 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826
	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 – Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, non-vPro, supporting gigabit file transfer speeds) non-vPro	
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax



	IEEE 802.11d			
	IEEE 802.11e			
	IEEE 802.11h			
	IEEE 802.11i			
	IEEE 802.11k			
	IEEE 802.11r			
	IEEE 802.11v			
Interoperability	Features Wi-Fi 6 technology			
Frequency Band	802.11b/g/n/ax			
	• 2.402 – 2.482 GHz			
	802.11a/n/ac/ax			
	• 4.9 – 4.95 GHz (Japan)			
	• 5.15 – 5.25 GHz			
	• 5.25 – 5.35 GHz			
	• 5.47 – 5.725 GHz			
	• 5.825 – 5.850 GHz			
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps			
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps			
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps			
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)			
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)			
	• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)			
Modulation	Direct Sequence Spread Spectrum			
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM			
Security ³	• IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only			
	AES-CCMP: 128 bit in hardware			
	• 802.1x authentication			
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.			
	WPA2 certification			
	• IEEE 802.11i			
	• WAPI			
Network Architecture	Ad-hoc (Peer to Peer)			
Models	Infrastructure (Access Point Required)			
Roaming	IEEE 802.11 compliant roaming between access points			
Output Power ²	• 802.11b : +18.5dBm minimum			
	• 802.11g : +17.5dBm minimum			
	• 802.11a : +18.5dBm minimum			
	• 802.11n HT20(2.4GHz) : +15.5dBm minimum			
	• 802.11n HT40(2.4GHz) : +14.5dBm minimum			
	• 802.11n HT20(5GHz): +15.5dBm minimum			
	• 802.11n HT40(5GHz): +14.5dBm minimum			
	• 802.11ac VHT80(5GHz): +11.5dBm minimum			
	• 802.11ac VHT160(5GHz) : +11.5dBm minimum			
	• 802.11ax HT40(2.4GHz) : +10dBm minimum			
Dower Consumption	• 802.11ax VHT160(5GHz): +10dBm minimum • Transmit mode 2.0 W			
Power Consumption	Receive mode 1.6 W			
	Receive mode 1.6 w Idle mode (PSP) 180 mW (WLAN Associated)			
	Idle mode (PSP) 180 mw (WLAN ASSOCIATED) Idle mode 50 mW (WLAN unassociated)			
	Connected Standby 10mW Padio disabled 8 mW			
Dawey Mans somet	Radio disabled 8 mW ACRI and BCI Everyors compliant power management			
Power Management	ACPI and PCI Express compliant power management			
Dogainay Completeday?	802.11 compliant power saving mode			
Receiver Sensitivity ³	•802.11b, 1Mbps : -93.5dBm maximum			
	•802.11b, 11Mbps : -84dBm maximum			



	• 802.11a/g, 6Mb	os : -86dBm maximum			
	• 802.11a/g, 54Mbps : -72dBm maximum				
	• 802.11n, MCS07 : -67dBm maximum				
	• 802.11n, MCS15 : -64dBm maximum				
	• 802.11ac, MCS0	: -84dBm maximum			
	• 802.11ac, MCS9 : -59dBm maximum				
	•802.11ax, MCS1	(HT40): -59dBm maximum			
	•802.11ax, MCS1	(VHT160): -58.5dBm maximum			
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure				
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications				
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface				
Dimensions	1. Type 2230: 2.3				
		7 x 12.0 x 16.0 mm			
Weight	1. Type 2230: 2.8				
	2. Type 126: 1.3g				
Operating Voltage	3.3v +/- 9%				
Temperature	Operating	14° to 158° F (–10° to 70° C)			
	Non-operating	-40° to 176° F (-40° to 80° C)			
Humidity	Operating	10% to 90% (non-condensing)			
	Non-operating	5% to 95% (non-condensing)			
Altitude	Operating	0 to 10,000 ft (3,048 m)			
	Non-operating	0 to 50,000 ft (15,240 m)			
		LED Amber – Radio OFF; LED Off – Radio ON			
LED Activity		o OFF; LED Off – Radio ON			
HP Integrated Module with Blue	LED Amber – Rad	5.0/5.1 Wireless Technology			
HP Integrated Module with Blue Bluetooth® Specification	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5.	5.0/5.1 Wireless Technology			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz	5.0/5.1 Wireless Technology I Compliant			
HP Integrated Module with Blue Bluetooth® Specification	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5.	5.0/5.1 Wireless Technology 1 Compliant Hz/CH)			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy : 0~79 (1 M BLE : 0~39 (2 MHz/	5.0/5.1 Wireless Technology 1 Compliant Hz/CH)			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps da	5.0/5.1 Wireless Technology 1 Compliant Hz/CH) CH)			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps da BLE: 1 Mbps data r Legacy: Synchrono	5.0/5.1 Wireless Technology 1 Compliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps ous Connection Oriented links up to 3, 64 kbps, voice channels. hous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5)			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels	LED Amber – Rad 2tooth® 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps data is Legacy: Synchronous (1 May 1 and	5.0/5.1 Wireless Technology 1 Compliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps ous Connection Oriented links up to 3, 64 kbps, voice channels. hous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5)			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput	LED Amber – Rad 2tooth® 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps data is Legacy: Synchronous (1 May 1 and	5.0/5.1 Wireless Technology 1 Compliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps ous Connection Oriented links up to 3, 64 kbps, voice channels. hous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps da BLE: 1 Mbps data r Legacy: Synchrono Legacy: Asynchronor 864 kbps symm The Bluetooth® cotransmit power of	5.0/5.1 Wireless Technology 1 Compliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps ous Connection Oriented links up to 3, 64 kbps, voice channels. hous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps da BLE: 1 Mbps data i Legacy: Synchrono Legacy: Asynchronor 864 kbps symm The Bluetooth® cotransmit power of Peak (Tx) 330 mW	5.0/5.1 Wireless Technology 1 Compliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps ous Connection Oriented links up to 3, 64 kbps, voice channels. ious Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR.			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps data in Legacy: Synchronic Legacy: Asynchronic Legacy: Asynchronic Regacy: Asynchronic Synchronic Legacy: Asynchronic Legacy: Asynchronic Regacy: Asynchronic Regacy: Asynchronic Synchronic Legacy: Asynchronic Regacy: Asynchronic Regacy: Asynchronic Legacy: Asynchronic Regacy: Asynchro	5.0/5.1 Wireless Technology 1 Compliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps ous Connection Oriented links up to 3, 64 kbps, voice channels. ious Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR.			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Power Consumption Bluetooth® Software Supported	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps da BLE: 1 Mbps data r Legacy: Synchrono Legacy: Asynchronor 864 kbps symm The Bluetooth® contransmit power of Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend Microsoft Windows	5.0/5.1 Wireless Technology 1 Compliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps ous Connection Oriented links up to 3, 64 kbps, voice channels. hous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR.			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Power Consumption Bluetooth® Software Supported Link Topology Power Management	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps data is Legacy: Synchronic Legacy: Synchronic Legacy: Asynchronic Legacy: Asynchronic Regacy: Asynchronic Alegacy: Asynchronic Legacy: Asynchronic Regacy: Asynchronic Alegacy: Asynchronic Regacy: Asynchronic Legacy: Asynchron	Tompliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps bus Connection Oriented links up to 3, 64 kbps, voice channels. bous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR. 17 mW Seluetooth® Software 6 ACPI, and USB Bus Support			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Power Consumption Bluetooth® Software Supported Link Topology	LED Amber – Rad 2tooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps data in Legacy: Synchronic Legacy: Asynchronic Legacy: Asynchronic Regacy: Asynchronic Legacy: Asynchronic Regacy: Asynchronic Alegacy: Asynchronic Regacy: Asynchronic Legacy: Asynchronic Legacy: Asynchronic Legacy: Asynchronic Legacy: Synchronic Legacy: Synchroni	5.0/5.1 Wireless Technology 1 Compliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps ous Connection Oriented links up to 3, 64 kbps, voice channels. ous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR. 17 mW Bluetooth® Software 6 ACPI, and USB Bus Support 5C, Section 15.247 & 15.249			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Power Consumption Bluetooth® Software Supported Link Topology Power Management	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps data in Legacy: Synchronic Legacy: Asynchronic Legacy: Asynchronic Regacy: Asynchronic Asynchronic Legacy: Asynchronic Legacy: Asynchronic Regacy: Asynchronic Asynchronic Legacy: Asynchronic Legacy: Asynchronic Legacy: Asynchronic Legacy: Asynchronic Legacy: Synchronic Legacy: Sync	5.0/5.1 Wireless Technology I Compliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps aus Connection Oriented links up to 3, 64 kbps, voice channels. aus Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR. 17 mW S Bluetooth® Software 5 ACPI, and USB Bus Support 5 C, Section 15.247 & 15.249 800 826			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Power Consumption Bluetooth® Software Supported Link Topology Power Management	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps data in the second of the s	5.0/5.1 Wireless Technology I Compliant Hz/CH) CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps ate; throughput up to 0.2 Mbps aus Connection Oriented links up to 3, 64 kbps, voice channels. aus Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR. 17 mW Bluetooth® Software 5 ACPI, and USB Bus Support 5 C, Section 15.247 & 15.249 and 826 ive IEC60950			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Power Consumption Bluetooth® Software Supported Link Topology Power Management Certifications	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps da BLE: 1 Mbps data r Legacy: Synchrono Legacy: Asynchrono Legacy: Asynchronor Red kbps symm The Bluetooth® co transmit power of Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend Microsoft Windows FCC (47 CFR) Part 1 ETS 300 328, ETS 3 Low Voltage Direct UL, CSA, and CE Ma	5.0/5.1 Wireless Technology I Compliant Hz/CH) (CH) Ita rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps ous Connection Oriented links up to 3, 64 kbps, voice channels. ous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR. 17 mW Bluetooth® Software 6 ACPI, and USB Bus Support 5 C, Section 15.247 & 15.249 600 826 ive IEC60950 rk			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Power Consumption Bluetooth® Software Supported Link Topology Power Management	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps da BLE: 1 Mbps data is Legacy: Synchrono Legacy: Asynchrono Regacy: Asyn	5.0/5.1 Wireless Technology I Compliant Hz/CH) (CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps bus Connection Oriented links up to 3, 64 kbps, voice channels. bus Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR. 17 mW Bluetooth® Software 6 ACPI, and USB Bus Support 5C, Section 15.247 & 15.249 600 826 ive IEC60950 rk			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Power Consumption Bluetooth® Software Supported Link Topology Power Management Certifications	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps da BLE: 1 Mbps data r Legacy: Synchrono Legacy: Asynchrono Regacy: Async	5.0/5.1 Wireless Technology I Compliant Hz/CH) (CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps bus Connection Oriented links up to 3, 64 kbps, voice channels. bus Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR. 17 mW Bluetooth® Software 6 ACPI, and USB Bus Support 5C, Section 15.247 & 15.249 600 826 ive IEC60950 rk			
HP Integrated Module with Blue Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Power Consumption Bluetooth® Software Supported Link Topology Power Management Certifications	LED Amber – Rad etooth® 4.0/4.1/4.2/ 4.0/4.1/4.2/5.0/5. 2402 to 2480 MHz Legacy: 0~79 (1 M BLE: 0~39 (2 MHz/ Legacy: 3 Mbps da BLE: 1 Mbps data is Legacy: Synchrono Legacy: Asynchrono Regacy: Asyn	5.0/5.1 Wireless Technology I Compliant Hz/CH) (CH) ta rate; throughput up to 2.17 Mbps ate; throughput up to 0.2 Mbps bus Connection Oriented links up to 3, 64 kbps, voice channels. bus Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) etric (3-EV5) mponent shall operate as a Class II Bluetooth® device with a maximum +9.5 dBm for BR and EDR. 17 mW Bluetooth® Software 6 ACPI, and USB Bus Support 5C, Section 15.247 & 15.249 600 826 ive IEC60950 rk			



Technical Specifications – Networking and Communications

Levere and the second s
LE L2CAP Connection Oriented Channels
Train Nudging & Interlaced Scan
BT4.2 ESR08 Compliance
LE Secure Connection- Basic/Full
LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 –Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi + BT5				
Wireless LAN Standards	IEEE 802.11a			
	IEEE 802.11b			
	IEEE 802.11g			
	IEEE 802.11n			
	IEEE 802.11ac			
	IEEE 802.11d			
	IEEE 802.11e			
	IEEE 802.11h			
	IEEE 802.11i			
	IEEE 802.11k			
	IEEE 802.11r			
	IEEE 802.11v			
Interoperability	Wi-Fi® certified			
Frequency Band	802.11b/g/n			
	• 2.402 – 2.482 GHz			
	802.11a/n/ac			
	• 4.9 – 4.95 GHz (Japan)			
	• 5.15 – 5.25 GHz			
	• 5.25 – 5.35 GHz			
	• 5.47 – 5.725 GHz			
	• 5.825 – 5.850 GHz			
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps			
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps			
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps			
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)			
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)			
Modulation	Direct Sequence Spread Spectrum			
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM			
Security ³	IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only			
	AES-CCMP: 128 bit in hardware			
	802.1x authentication			
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.			
	WPA2 certification			
	• IEEE 802.11i			
Naturauli Aughita ataura	• WAPI			
Network Architecture	Ad-hoc (Peer to Peer)			
Models	Infrastructure (Access Point Required)			
Roaming	IEEE 802.11 compliant roaming between access points			
Output Power ²	• 802.11b : +18.5dBm minimum			
	• 802.11g: +17.5dBm minimum			
	• 802.11a : +18.5dBm minimum			





Technical Specifications – Networking and Communications

		.4GHz): +15.5dBm minimum		
	• 802.11n HT40(2.4GHz): +14.5dBm minimum			
	• 802.11n HT20(5GHz): +15.5dBm minimum			
		GHz): +14.5dBm minimum		
		O(5GHz): +11.5dBm minimum		
		50(5GHz) : +11.5dBm minimum		
Power Consumption	 Transmit mode : 	2.0 W		
	• Receive mode :1	· ·		
		180 mW (WLAN Associated)		
		W (WLAN unassociated)		
		dby/Modern Standby: 10mW		
	Radio disabled: 8			
Power Management		ess compliant power management		
		power saving mode		
Receiver Sensitivity ³		-93.5dBm maximum		
		: -84dBm maximum		
		s : -86dBm maximum		
		ps : -72dBm maximum		
	-	-67dBm maximum		
	-	-64dBm maximum		
		-84dBm maximum		
		-59dBm maximum		
Antenna type	High efficiency an	tenna with spatial diversity, mounted in the display enclosure		
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN			
	MIMO communica	tions and Bluetooth communications		
Form Factor	•	1iniCard with CNVi Interface		
Dimensions		x 22.0 x 30.0 mm		
		7 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8g			
	2. Type 126: 1.3g			
Operating Voltage	3.3v +/- 9%	T		
Temperature	Operating	14° to 158° F (–10° to 70° C)		
	Non-operating	−40° to 176° F (−40° to 80° C)		
Humidity	Operating	10% to 90% (non-condensing)		
	Non-operating	5% to 95% (non-condensing)		
Altitude	Operating	0 to 10,000 ft (3,048 m)		
	Non-operating	0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Rad	io OFF;		
	LED OFF – Radio O)N		
HP Integrated Module with Blu	etooth® 4.0/4.1/4.2	2/5.0 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0 Co	mpliant		
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	Legacy : 0~79 (1 M	Hz/CH)		
-	BLE: 0~39 (2 MHz/CH)			
Data Rates and Throughput		ita rate; throughput up to 2.17 Mbps		
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps			
		ous Connection Oriented links up to 3, 64 kbps, voice channels		
		nous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) o		
	864 kbps symmetr			
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum			
	transmit power of	+4 dBm for BR and EDR.		



Technical Specifications – Networking and Communications

Power Consumption	Peak (Tx) 330 mW		
- oner consumption	Peak (Rx) 230 mW		
	Selective Suspend 17 mW		
Bluetooth® Software Supported	Microsoft Windows Bluetooth® Software		
Link Topology			
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826		
	Low Voltage Directive IEC950		
	UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance		
	LE Link Layer Ping		
	LE Dual Mode		
	LE Link Layer		
	LE Low Duty Cycle Directed Advertising		
	LE L2CAP Connection Oriented Channels		
	Train Nudging & Interlaced Scan		
	BT4.2 ESR08 Compliance		
	LE Secure Connection- Basic/Full		
	LE Privacy 1.2 –Link Layer Privacy		
	LE Privacy 1.2 –Extended Scanner Filter Policies		
	LE Data Packet Length Extension		
	FAX Profile (FAX)		
	Basic Imaging Profile (BIP)2		
	Headset Profile (HSP)		
	Hands Free Profile (HFP)		
	Advanced Audio Distribution Profile (A2DP)		



Technical Specifications – Input/Output Devices

I/O DEVICES

HP Wired Desktop 320K K	eyboard			
Physical Characteristics	Keys	104, 105, 107, 109 layout (depending on country)		
	Dimensions (L x W x H)	16.77 x 4.36 x 0.65 in (426.2 x 110.9 x 16.7 mm)		
	Weight	14.57 oz (413g)		
	Cable length	6 ft. (1.8 m)		
Electrical	Operating voltage	5V		
	Power consumption	50mA - 100 mA		
	System interface	USB		
Mechanical	Keycaps	Low-profile design		
	Switch actuation	60±10g nominal peak force with tactile feedback		
	Switch life	10 million keystrokes (Life tester)		
	Switch type	Plunger		
Environmental				
	Operating temperature	50° to 122° F (10° to 50° C)		
	Non-operating temperature	-22° to 149° F (-30° to 65° C)		
	Operating humidity	10% to 90% (non-condensing at ambient)		
	Non-operating humidity	0% to 90% (non-condensing at ambient)		
Approvals	FCC, ICES, CULus, CE, GS, EAC, Ukraine, India BIS, KCC, RCM, BSMI, VCCI			
Ergonomic compliance	TUVGS			
Kit contents	Keyboard, QSP, Warranty Card, Product Notice			

HP USB Premium Keyboard				
	Keys	104, 105 layout (depending upon country)		
Physical Characteristics	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)		
	Weight	1.54 lb. (698g)		
	Operating voltage	5 VDC, +/-5%		
	Power consumption	35mA (All LED on)		
Electrical	System interface	USB Type A plug connector		
Electricat	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV		
	EMI - RFI	Conforms to FCC rules for a Class B computing device		
	Microsoft® PC 99 - 2001	Functionally compliant		
Mechanical	Keycaps	Low-profile design		
rieciiaiiicat	Switch actuation	60±10g nominal peak force with tactile feedback		



Technical Specifications – Input/Output Devices

Switch life	10 million keystrokes (Life tester)		
Switch type	Contamination-resistant switch membrane		
Key-leveling mechanisms	For all double-wide and greater-length keys		
Cable length	6 ft. (1.8 m)		
Microsoft PC 99 - 2001	Mechanically compliant		
Acoustics	43-dBA maximum sound pressure level		
Operating temperature	50° to 122° F (10° to 50° C)		
Non-operating temperature	-22° to 140° F (-30° to 60° C)		
Operating humidity	10% to 90% (non-condensing at ambient)		
Non-operating humidity	20% to 80% (non-condensing at ambient)		
Operating shock	40 g, six surfaces		
Non-operating shock	80 g, six surfaces		
Operating vibration	2-g peak acceleration		
Non-operating vibration	4-g peak acceleration		
Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence		
Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence		
UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC			
TUVGS			
Keyboard, QSP			
Product Notice			
	Key-leveling mechanisms Cable length Microsoft PC 99 - 2001 Acoustics Operating temperature Non-operating temperature Operating humidity Non-operating humidity Operating shock Non-operating shock Operating vibration Non-operating vibration Drop (out of box) Drop (in box) UL, FCC, CE Mark, TUV GS, VCCI, TUVGS Keyboard, QSP		

HP Wired Desktop 320M	Mouse		
Dimensions (H x L x W)	4.08 x 2.49 x 1.39 in (103.8 x 63.4 x 35.5 mm)		
Weight	2.67 oz (75.8 g)		
Mechanical	Connector	USB	
	Resolution	1000 DPI	
	Sensor	Optical Red Sensor	
Tracking speed	Tracking acceleration	8G(max), 1G=9.8m/s2	
	Cable length	6 ft. (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	FCC, ICES, CULus, CE, GS, EAC, Ukraine. India BIS, KCC, RCM, BSMI, VCCI	

Technical Specifications – Input/Output Devices

HP USB Premium Mouse			
Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)		
Weight	0.19lb (90g)		
Environmental	Operating temperature	50° to 122°F (10° to 50° C)	
	Non-operating temperature	-22° to 140°F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	50 g, 6 surfaces	
	Non-operating shock	80 g, 6 surfaces	
	Operating vibration	2 g peak acceleration	
	Non-operating vibration	4 g peak acceleration	
Electrical	Operating voltage	5 VDC, +/-5%	
	Power consumption	12mA	
Mechanical	Connector	USB 2.0	
	Туре	3D mouse (3 keys and wheel)	
	Resolution	800, 1200, 1600 DPI	
	Sensor	Pixart PAN3606DL	
Tracking speed	Tracking acceleration	8G(max), 1G=9.8m/s2	
	Cable length	6 ft. (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC	

HP USB Mouse				
Dimensions (H x L x W)	37mm x 115mm x 62.9mm	37mm x 115mm x 62.9mm		
Weight	90 +10g/- 5 g	90 +10g/- 5 g		
Color	Black	Black		
Connector	USB			
Marka Carl	Resolution	800 DPI sensitivity		
Mechanical	Buttons	Two primary buttons and clickable scroll wheel		

Technical Specifications – Audio/Multimeda

AUDIO/MULTIMEDIA

HP EliteDesk 800 G6 Tower Business PC

Type Integrated

HD Stereo Codec Conexant CX20632 / Realtek ALC 3867

Audio I/O Ports Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

1 - Headphone port Rear: 1 - Line-out

1 - Line-in which is retaskable as a Microphone Input

All ports are 3.5mm and support stereo

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent aud

Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

HP EliteDesk 800 G6 Small Form Factor Business PC

Type Integrated

HD Stereo Codec Conexant CX20632 / Realtek ALC 3867

Audio I/O Ports Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

1 - Headphone port Rear: 1 - Line-out

1 - Line-in which is retaskable as a Microphone Input

All ports are 3.5mm and support stereo

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

Playback multi-streaming can be enabled in the audio control panel to allow independent audio

Multi-streaming Capable streams to be sent to/from the front and rear jacks or integrated speaker.

Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes



Sampling

Technical Specifications – Audio/Multimeda

HP EliteDesk 800 G6 Desktop Mini Business PC

Type Integrated

HD Stereo Codec Realtek ALC3205-CG / Realtek ALC 3867

Audio I/O Ports combo audio jack with CTIA and headset support

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

HP EliteOne 800 G6 24 & 27 All-in-One

Bang & Olufsen Audio

Type Integrated

HD Stereo Codec Realtek ALC3274

Side headset connector supports a CTIA/OMTP style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

Side headphone connector supports a headphone connections

Rear line out connector

Audio I/O Ports All ports are 3.5mm and support stereo

Internal Speaker Amplifier 5W per channel class D stereo amplifier for the internal speakers only

Playback multi-streaming can be enabled in the audio control panel to allow independent audio

Multi-streaming Capable streams to be sent to/from the front and rear jacks or integrated speakers.

Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

Sampling to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes - Stereo



Technical Specifications – Integrated Webcam and Microphone

INTEGRATED WEBCAM AND MICROPHONE

Integrated Webcam and Microphone

Optional integrated 5 MP Full HD RGB webcam & microphone; maximum resolution of 2624 x 1976
Optional integrated 5 MP Full HD RGB dual-facing webcam with IR sensor (user-facing) & microphone; maximum resolution of 2624 x 1976

NOTE: All HP devices which carry the Bang & Olufsen brand are custom-tuned with Bang & Olufsen's acoustical engineers for precise sound experience in business use.

INTEGRATED FINGERPRINT SENSOR

Sensor type: Touch

Fingerprint matching: Performed on device

Anti-Spoofing: Yes

Windows Hello Support: Yes Encryption: On sensor FIPS Compliant: No



Technical Specifications – Power

POWER

HP EliteDesk 800 G6 Tower Business PC

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 95% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 SFF Business PC

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 95% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (35W)

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (65W)

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (95W)

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)



Technical Specifications – Power

HP EliteOne 800 G6 24 & 27 All-in-One

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~45°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

	DM	SFF	TWR	AiO
External Power Supplies	65W EPS, 88% average efficiency at 115V & 89% at 230Vac 90W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac 150W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac	N/A	N/A	N/A
80 PLUS Gold	N/A	N/A	N/A	N/A
80 PLUS Platinum		350W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	PLUS Platinum 350W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V)	210W active PFC / 80 PLUS Platinum 280W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ
Operating Line Frequency	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ
Rated Input Current				
Energy Efficient* Power	65W≦1.6A 90W≦1.7A 150W≦2.5A	260W Platinum≤3.1A 350W Platinum≤4A	260W Platinum≤3.1A 350W Platinum≤4.2A 550W Platinum≤6.6A	210W ≦2.8A 280W≦3.2A



Technical Specifications – Power

	DM	SFF	TWR	AiO
Current Leakage (NFPA 99:	Less than 500	Less than 500	Less than 500	Less than 500
2012)	microamps of leakage	microamps of leakage	microamps of leakage	microamps of leakage
	current at 120 Vac with	current at 120 Vac with	current at 120 Vac with	current at 120 Vac with
	the ground wire	the ground wire	the ground wire	the ground wire
	disconnected, as	disconnected, as		disconnected, as
		required for Non-patient		
	Electrical Appliances		• •	patient Electrical
	and Equipment used in a		and Equipment used in a	
	patient care facility or	patient care facility or	patient care facility or	Equipment used in a
	that contact patients in	that contact patients in	<u>-</u>	patient care facility or
	normal use. Per section	normal use. Per section		that contact patients in
	10.3.5.1.	10.3.5.1.	10.3.5.1.	normal use. Per section
	Less than 100		Less than 100	10.3.5.1.
	microamps of leakage	microamps of leakage		Less than 100
	current at 120 Vac with	current at 120 Vac with		microamps of leakage
	the ground wire intact	the ground wire intact	the ground wire intact	current at 120 Vac with
	with normal polarity, as	with normal polarity, as		the ground wire intact
		required for Non-patient		
	Electrical Appliances			required for Non-
		and Equipment used in a		
	patient care facility or that contact patients in	patient care facility or that contact patients in		Appliances and Equipment used in a
	normal use. Per section	normal use. Per section		patient care facility or
	10.3.5.1.	10.3.5.1.		that contact patients in
	10.3.3.1.	10.3.3.1.	10.3.3.1.	normal use. Per section
				10.3.5.1.
Power Supply Fan	N/A	70mm variable speed	70mm variable speed	N/A
	-	•		-
Power cord length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)		6.0 ft. (1.83 m)
External Power Adapter	External power supply	Internal power supply	Internal power supply	Internal power supply
Dimensions	65W: 90 x 51 x 28.5mm	165 x 95 x 73mm	165 x 95 x 73mm	110 x 110 x 26mm
	& 102 x 55 x 30mm			
	90W: 126 x 50 x 30mm			
	150W: 148 x 75.5 x			
	25.4mm			
Total Cord Length	6.0 ft. (1.83m)	6.0 ft. (1.83m)	6.0 ft. (1.83m)	6.0 ft. (1.83m)

Technical Specifications – Power

The power supply shall comply with harmonic input current requirements as detailed in EN61000-3-2 and JEIDA MITI standards. The harmonic input current requirements must be met under the following operating conditions: Load Requirements: 50% and 100%

Input Voltage: 230Vac/50Hz.

For active power factor correction the power factor at 50% &100% loads shall be greater than 0.9 over the entire nominal input voltage range (100-127VAC and 200-240VAC).

Condition	Standard Efficiency	82/85/82%	85/88/85%	87/90/87%	90/92/89%	Input Voltage
10% of Rated Load	-	75%	81%	84%	86%	115Vac/60HZ
20% of Rated Load	-	82%	85%	87%	90%	115Vac/60HZ
50% of Rated	-	85%	88%	90%	92%	115Vac/60HZ
Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.95	
100% of Rated	70%	82%	85%	87%	89%	115Vac/60HZ
Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.9	230Vac/50HZ



Technical Specifications – Weights and Dimensions

WEIGHTS & DIMENSIONS

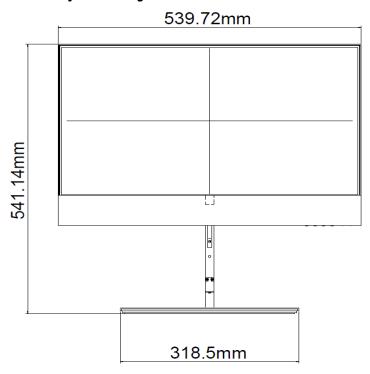
	DM	SFF	TWR	AiO
Chassis (W x D x H)	6.97 x 6.89 x 1.35in 177 x 175 x 34mm	13.3 x 12.13 x 3.94in 338 x 308 x 100mm	14.57 x 12.13 x 6.61in 370 x 308 x 168mm	See table below.
System Volume	63.4 cu in 1.05L	634.6 cu in 10.4 L	1186.8 cu in 19.14 L	See table below.
System Weight	3.13lb 1.42kg	13.5lb 6.13kg	21.74lb 9.86kg	See table below.
Max Supported Weight (desktop orientation)	: 0	77lb 35kg	77lb 35kg	See table below.
Stand Dimensions	160 x 117 x 18.5mm	151.8 x 200 x 37.2mm	N/A	See table below.
Packaging (W x D x H)	19.6 x 9.3 x 5.2in 498 x 235 x 132mm	15.71 x 19.65 x 9.06in 399 x 499 x 230mm	19.65 x 11.61 x 18.62in 499 x 295 x 473mm	See table below.
Shipping Weight	2.95kg 6.49lb	7.683kg 16.92lb	9.058kg 19.95lb	See table below.
Multipack Packaging (10 units)	20.28 x16.54 x 25in 515 x 420 x 63 mm			
Palletization Profile	10 units per layer 17 layers max 170 units per pallet 46.3 x 39.2 x 94.1in, 1175 x 996 x 2389mm (include pallet)	6 units per layer 10 layers max 60 units per pallet 1200 x 1000 x 2438mm (include the pallet)	8 units per layer 5 layers ax 40 units per pallet 1200 x 1000 x 2495mm (include the pallet)	10-units per layer 4-layers max 40-units per pallet (sea) 1200 x 1000 x 2470mm

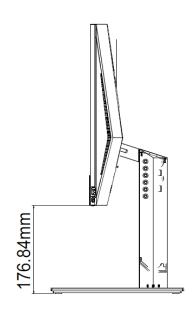


Technical Specifications – Weights and Dimensions

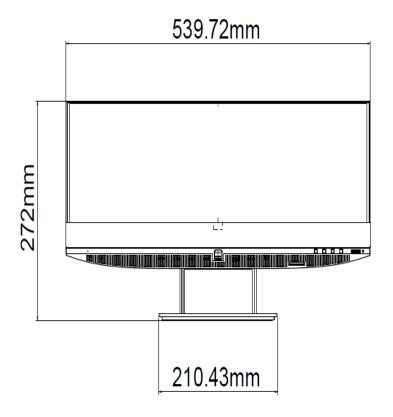
STANDS AND DIMENSIONS

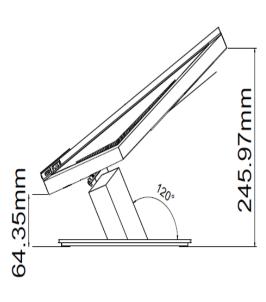
HP EliteOne G6 AIO Adjustable Height Stand - 23.8"





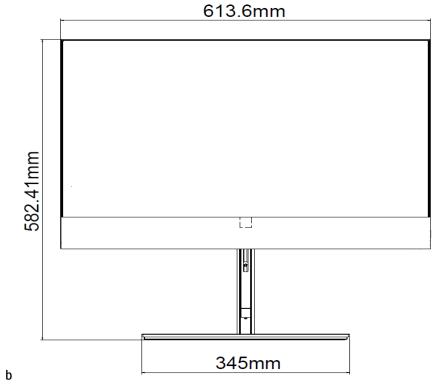
HP EliteOne G6 AIO Recline Stand - 23.8"

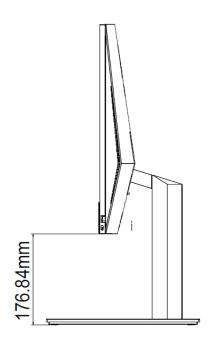




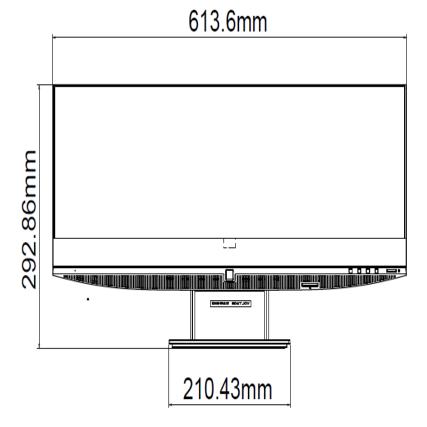
Technical Specifications – Weights and Dimensions

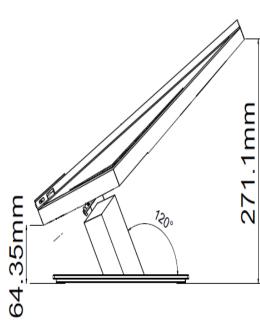
HP EliteOne G6 AIO Adjustable Height Stand - 27"





HP EliteOne G6 AIO Recline Stand - 27"





Technical Specifications – Weights and Dimensions

Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)	
	Portrait Adjustment	No portrait	
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait	
	Rotation (Swivel)	90° (±1°) (45 left, 45 right)	
	Pivot	No pivot	

Recline Stand:	Height - Vertical Adjustment	No height	
Tilt Angle		+36.5° to +58° (+/-1.5°)	
	Rotation (swivel)	No swivel	



Technical Specifications – Weights and Dimensions

ALL-IN-ONE WEIGHTS AND DIMENSIONS

Weight without Touch Panel - 23.8"

Product Weight Unboxed	15.12 lbs. 6.86 kg	Stand	Recline Stand 18.83 lbs. 8.54 Kg
Shipping Weight Boxed	19.51 lbs.	Stand	Recline Stand 23.08 lbs. 10.47 kg
Shipping Weight Pallet (30 units)	623.7 lbs.	Stand	Recline Stand 730.62 lbs. 332.1 kg

Weight with Touch Panel - 23.8"

Product Weight Unboxed	Without Stand 17.50 lbs. 7.94 kg	Adjustable Height Stand 22.84 lbs. 10.36 kg	Recline Stand 21.21 lbs. 9.62 Kg
Shipping Weight Boxed	Without Stand 21.89 lbs. 9.93 kg	Adjustable Height Stand 27.23 lbs. 12.35kg	Recline Stand 25.46 lbs. 11.55 kg
Shipping Weight Pallet (30 units)	Without Stand 694.98 lbs. 315.9 kg	Adjustable Height Stand 854.7lbs. 388.5kg	Recline Stand 801.9lbs. 364.5 kg

Dimensions (W \times D \times H) – 23.8"

539.72 x 364.3 x 57.3 mm	Stand (-5 ~ 20) degrees	Recline Stand Stand (30 ~ 60) degrees 539.72 x 379.44 x 209.35 mm
539.72 x 364.3 x 59.3 mm	Stand (-5 ~ 20) degrees	Recline Stand Stand (30 ~ 60) degrees 539.72 x 379.44 x 211.35 mm

Shipping Dimensions - 23.8"

- 11 3	11		Recline Stand 628 x 186 x 635 mm
Shipping	Without Stand	Adjustable Height	Recline Stand
Dimensions	1180 x 874 x 2060 mm	1180 x 874 x 2060 mm	1180 x 874 x 2060 mm
Pallet			
Pallet (40 units)			



Technical Specifications – Weights and Dimensions

Weight with Touch Panel - 27"

Product Weight Unboxed	Without Stand 19.56 lbs. 8.87 kg	Adjustable Height Stand 25.40 lbs. 11.52 kg	Recline Stand 23.26 lbs. 10.55 Kg
Shipping Weight Boxed	Without Stand 25.46 lbs. 11.55 kg	Adjustable Height Stand 31.31 lbs. 14.2 kg	Recline Stand 29.17 lbs. 13.23 kg
Shipping Weight Pallet (18 units)	Without Stand 496.98 lbs. 225.9 kg	Adjustable Height Stand 601.92 lbs. 273.6 kg	Recline Stand 563.5 lbs. 256.14 kg

Weight without Touch Panel - 27"

Product Weight Unboxed	Without Stand 17.79 lbs. 8.07 kg	Adjustable Height Stand 23.63 lbs. 10.72 kg	Recline Stand 21.50 lbs. 9.75 Kg
Shipping Weight Boxed	Without Stand 23.70 lbs. 10.75 kg	Adjustable Height Stand 29.54 lbs. 13.4 kg	Recline Stand 27.40 lbs. 12.43 kg
Shipping Weight Pallet (18 units)	Without Stand 465.3 lbs. 211.5 kg	Adjustable Height Stand 570.24 lbs. 259.2 kg	Recline Stand 531.83 lbs. 241.74 kg

Dimensions (W x D x H) - 27"

613.6 x 405.57 x 58.7 mm	Stand (-5 ~ 20) degrees	Recline Stand Stand (30 ~ 60) degrees 613.6 x 420.71 x 210.68 mm
613.6 x 405.57 x 59.07 mm	Stand (-5 ~ 20) degrees	Recline Stand Stand (30 ~ 60) degrees 613.6 x 420.71 x 211.05 mm

Shipping Dimensions – 27"

- 11 3	742 x 237 x 640 mm	.,	Recline Stand 742 x 237 x 640 mm
		,	Recline Stand 1180 x 958 x 2076 mm



Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adaptor could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / PCA failure
 - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software
- Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal (For MT, SFF, and DM only)
- · Green Pull Tabs, and Quick Release Latches for easy Identification



Technical Specifications – Miscellaneous Features

Additional Features	Description
Tower Orientation	Product can be oriented as either a desktop (horizontal) or a tower (vertical) for MT, SFF, and DM only. SFF/DM requires optional stand.
Drive Lock	Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.
Boot Sectors Protection	MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.
Drive Protection System	DPS Access through F10 Setup during Boot (for SATA hard drive only)
	A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user
	Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced
	The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted
SMART I - Drive Failure Prediction	Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count
SMART II - Off-Line Data Collection	By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure
SMART III - Off-Line Read Scanning with Defect Reallocation	IOEDC: I/O Error Detection Circuitry
SMART IV - End-to-End CRC for hard drives	Detects errors in Read/Write buffers on HDD cache RAM



Technical Specifications – After Market Options

AFTER MARKET OPTIONS

Graphics Solutions	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	Part Number
AMD® Radeon™ RX 550X 4GB Display Port Card		X			5LH79AA
AMD® Radeon™ R7 430 2GB 2 Display Port Card		X	X		5JW82AA
AMD® Radeon™ R7 430 2GB DP+VGA Card		X	X		5JW81AA

Desktop Mini Accessories	<u>DM</u>	SFF	MT	<u>AiO</u>	Part Number
HP Desktop Mini Port Cover v3	<u>X</u> (95W and discrete GPU skus not supported)				13L69AA
HP Desktop Mini 2.5" SATA Drive Bay kit v2	<u>X</u> (95W and discrete GPU skus not supported)				13L70AA
HP Desktop Mini 65W Power Supply Kit	<u>X</u>				L2X04AA
HP Desktop Mini 90W Power Supply Kit	<u>X</u>				L4R65AA
HP Desktop Mini LockBox V2	<u>X</u> (95W and discrete GPU skus not supported)				3EJ57AA
HP Desktop Mini DVD-Writer ODD Expansion Module	V (Fither and)				K9Q83AA
HP Desktop Mini I/O Expansion Module	X (Either one)				K9Q84AA
HP Desktop Mini Security/Dual VESA Sleeve v3	(95W and discrete GPU skus not supported)				13L67AA
HP Desktop Mini Security/Dual VESA Sleeve v3 with Power Supply Holder	<u>X</u> (95W and discrete GPU skus not supported)				13L68AA
HP B250 PC Mounting Bracket	<u>X</u>				<u>8RA46AA</u>
HP B300 PC Mounting Bracket	<u>X</u>				2DW53AA
HP B300 PC Mounting Bracket with Power Supply Holder	<u>X</u> (95W and discrete GPU skus not supported)				7DB37AA
HP B500 PC Mounting Bracket	<u>X</u>				<u>2DW52AA</u>
HP Desktop Mini Vertical Chassis Stand	<u>X</u>				<u>G1K23AA</u>
HP DM Power Supply Holder Kit v2	<u>X</u> (95W and discrete GPU skus not supported)				<u>7DB38AA</u>
HP Quick Release Bracket 2	X			<u>X</u> (required pre- configured VESA adapter	<u>6KD15AA</u>
HP Single Monitor Arm	<u>X</u>			<u>X</u>	<u>BT861AA</u>



Technical Specifications – After Market Options

Data Storage Drives	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP PCIe NVME TLC 256GB SSD M.2 Drive	X	X	X	X	1CA51AA
HP PCIe NVME TLC 512GB SSD M.2 Drive	X	X	X	X	X8U75AA
HP 500GB 7200PRM SATA 3.5" Hard Drive		X	X		QK554AA
HP 1TB 7200rpm SATA 3.5" Hard Drive		X	X		QK555AA
HP SFF SATA DVD-Writer ODD		X			52D76AA
HP TWR SATA DVD-Writer ODD			X		52D77AA

Input Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part</u> Number
HP Desktop Wired 320K Keyboard	Х	X	Х	X	9SR37AA
HP Desktop Wired 320M Mouse	Х	Х	Х	Х	9VA80AA
HP Desktop Wired 320MK Mouse and Keyboard	Х	Х	Х	Х	9SR36AA
HP USB Antimicrobial Business Slim Keyboard and Mouse	Х	Х	Х	Х	Z9H50AA
HP USB Business Slim CCID SmartCard Keyboard	X	Х	Х	X	Z9H48AA
HP USB Keyboard	Х	Х	Х	Х	QY776AA
HP USB Keyboard and Mouse Healthcare Edition	Х	Х	Х	X	1VD81AA
HP USB Premium Keyboard	X	Х	Х	X	Z9N40AA
HP USB PS/2 Washable Keyboard & Mouse	X	Х	Х	X	BU207AA
HP Wireless Business Slim Keyboard and Mouse	Х	Х	Х	X	N3R88AA
HP Wireless Premium Keyboard	X	Х	Х	X	Z9N41AA
HP PS/2 Business Slim Keyboard		Х	Х		N3R86AA
HP USB Fingerprint Mouse	Х	Х	Х	X	4TS44AA
HP USB Premium Mouse	Х	Х	Х	Х	1JR32AA
HP PS/2 Mouse		Х	Х		QY775AA
HP Wireless Premium Mouse	X	Х	Х	X	1JR31AA
HP USB 1000dpi Laser Mouse	X	Х	X	X	QY778AA
HP USB Optical Mouse	Х	Х	Х	X	QY777AA
HP USB Hardened Mouse ¹	X	X	X	X	P1N77AA

1. Not available in all regions

System Memory	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part</u> <u>Number</u>
HP 32GB DDR4-2666 DIMM		Х	Х		1C918AA
HP 32GB DDR4-2666 SODIMM	X			X	1C919AA
HP 4GB DDR4-3200 UDIMM		Х	Х		13L78AA
HP 8GB DDR4-3200 UDIMM		Х	Х		13L76AA
HP 16GB DDR4-3200 UDIMM		Х	Х		13L74AA
HP 32GB DDR4-3200 UDIMM		Х	Х		13L72AA
HP 4GB DDR4-3200 SODIMM	X			X	13L79AA
HP 8GB DDR4-3200 SODIMM	X			X	13L77AA



Technical Specifications – After Market Options

HP 16GB DDR4-3200 SODIMM	X		X	13L75AA
HP 32GB DDR4-3200 SODIMM	X		Х	13L73AA

Multimedia Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP Business Headset v2	Х	Х	Х	X	T4E61AA
HP S101 Speaker Bar	Х	Х	Х		5UU40AA
HP UC Speaker Phone v2	Х	Х	Х		4VW02AA

Security Devices	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part</u> <u>Number</u>
HP Business PC Security Lock v3 Kit		Х	Х		3XJ17AA
HP Dual Head Keyed Cable Lock		Х	X		T1A64AA
HP Keyed Cable Lock 10mm	Х	Х	Х	X	T1A62AA
HP Master Keyed Cable Lock 10mm	Х	Х	Х	X	T1A63AA
HP Sure Key Cable lock	Х				6UW42AA

Stands and Accessories	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP EliteOne 800 G6 23.8" Height Adjustable Stand				х	13L61AA
HP EliteOne 800 G6 23.8" Recline Stand				Х	13L62AA
HP EliteOne 800 G6 27" Height Adjustable Stand				х	13L63AA
HP EliteOne 800 G6 27" Recline Stand				X	13L64AA

I/O Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP DisplayPort Port Flex IO v2	X	Х	X		13L54AA
HP HDMI Port Flex IO v2	X	Х	X		13L55AA
HP Type-C [®] USB 3.1 Gen2 Port Flex IO v2	X	Х	X		<u>13L59AA</u>
HP Type-C [®] USB 3.1 Gen2 Port with PD Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)				<u>13L60AA</u>
HP USB 3.1 Gen1 x2 Module Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)	х	х		13L58AA
HP VGA Port Flex IO v2	X	Х	X		<u>13L53AA</u>
HP Serial Port Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)	х	X		<u>13L56AA</u>

HP Serial Port Flex IO 2 v2	X (Not Available on 95W and discrete GPU SKUs)			<u>13L57AA</u>
HP Internal Serial Port (in rear wall)		Х	Х	3TK82AA



Technical Specifications – After Market Options

HP PCIe x1 Parallel Port Card		Х	X	N1M40AA
HP Serial/PS/2 Adapter Kit (in PCIe slot)		Х	X	1VD82AA
HP USB to Serial Port Adapter	X	Х	X	J7B60AA
HP USB-C to Display Port Adapter	X	Х	X	N9K78AA
HP Single Mini Display Port Adapter to Display Port Adapter	X (Only Available with GPU SKUs)			2MY05AA

NOTE: For more detail on HP I/O Devices please refer to the HP FLEX IO Option Cards QuickSpecs. URL is: http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06042607

Communication Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
Intel® Ethernet I210-T1 GbE NIC		Х	Х		<u>E0X95AA</u>

Intel® Optane Memory	<u>DM</u>		<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
512GB Intel® Optane™ Memory H10 with SSD	х	X	X	х	6VF55AA



Change Log

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Date	Version History	Action	Description of Change
July 15, 2020	From v1 to v2	Addition	Supported versions section
July 22, 2020	From v2 to v3	Addition	NVIDIA® GeForce® RTX 2070 Super 8GB GDDR6
August, 2020	From v3 to v4	Addition	DVD-R DL - Up to 6X, DVD+R DL - Up to 6X, DVD-R SL/DL Up to 8X and DVD+R SL/DL Up to 8X on the read/write speed on the blue ray write drive specs on Storage section. Specs for DM environmental section completed. DM rear call outs corrected.
October 6, 2020	From v4 to v5	Correction	ALL-IN-ONE WEIGHTS AND DIMENSIONS tables information.
October 7, 2020	From v5 to v6	Addition	Environmental specs for SFF
October 8, 2020	From v6 to v7	Update	Environmental specs for AiO 24
October 8, 2020	From v6 to v7	Update	Environmental specs for AiO 24
October 27, 2020	From v8 to v9	Correction	Processors footnotes and Turbo boost specs corrected
November 13, 2020	From v9 to v10	Addition	Specification at External Power Supplies row in POWER section
November 20, 2020	From v10 to v11	Correction	Rear components and rear ports call outs section and NVIDIA® GeForce® RTX 2070 Super 8GB GDDR6 specs corrected
November 26, 2020	From v11 to v12	Addition	Environmental specs for TWR
January 6, 2021	From v12 to v13	Update/add	Footnotes added to "At a glance" section and packaging materials data in 23.8-in All-in-One Environmental info updated
January 20, 2021	From v13 to v14	Correction	Intel® i210 10/100/1000 NIC in N&C section corrected
January 21, 2021	From v14 to V15	Removal	HP Thunderbolt 3.0 (4CX35AA) from AMO section
January 26, 2021	From v15 to v16	Correction	System volume for TWR and SFF in Weights and dimensions section
February 17, 2021	From v16 to v17	Correction	"Anti-glare" removed from 27.0" LCD (2560 x 1440) Touch in DISPLAY PANEL SPECIFICATIONS
February 24, 2021	From v17 to v18	Update	At a Glance section Raid bullet and Fiber NIC specification added
March 22, 2021	From v18 to v19	Update	Description added to HP Quick Release Bracket 2 in AMO
April 15, 2021	From v19 to v20	Update/ Correction	Disclaimer for Fiber NIC flex port card added in DM rear call outs/Typo in Power Supply section
April 20, 2021	From v20 to v21	Update	Intel® I219-LM 1 table
May 4, 2021	From v21 to v22	Addition	HP Smart Support and footnote added to software section
May 12, 2021	From v22 to v23	Removal	DM from HP Reverb VR Headset bullet in At a Glance section
June 9, 2021	From v23 to v24	Update	Audio/multimedia settings and call outs except for AIO's
July 2, 2021	From v24 to v25	Addition	10 new processors
July 6, 2021	From v25 to v26	Update	256GB Intel® PCIe® NVMe™ QLC + 16GB Intel® Optane from 32GB
August 6, 2021	From v26 to v27	Update	System memory in AMO updated
August 19, 2021	From v27 to v28	Update	Environmental, Weights and dimensions, Power, Miscellaneous features, display specifications and Storage updated.
November 4, 2021	From v28 to v29	Update	1CA52AA removed and replaced with 52D76AA and 52D77AA added in Data Storage Drives at Amo section.



HP EliteDesk 800 G6 and HP EliteOne 800 G6 Business Desktops PCs

QuickSpecs

Change Log

December 3, 2021	From v29 to v30	Update	Memory main table module updated Windows 11 upgrade added
March 28, 2022	From v30 to v31	Update	Front / Rear facing 5MP Webcam correction in call outs section
April 28, 2022	From v31 to v32	Correction	Slots for AiO corrected.
June 16, 2022	From v32 to v33	Update	Environmental tables certifications updated

